

# Lecture 08 - **HIGH-SPEED**

## **Advanced Layout: High-Speed**

# Outline

- **Introduction**
- **High-Frequency Routing**
- **High-Frequency Fabrication**
- **PCBs for Planar Microwave Devices**
- **Examples**

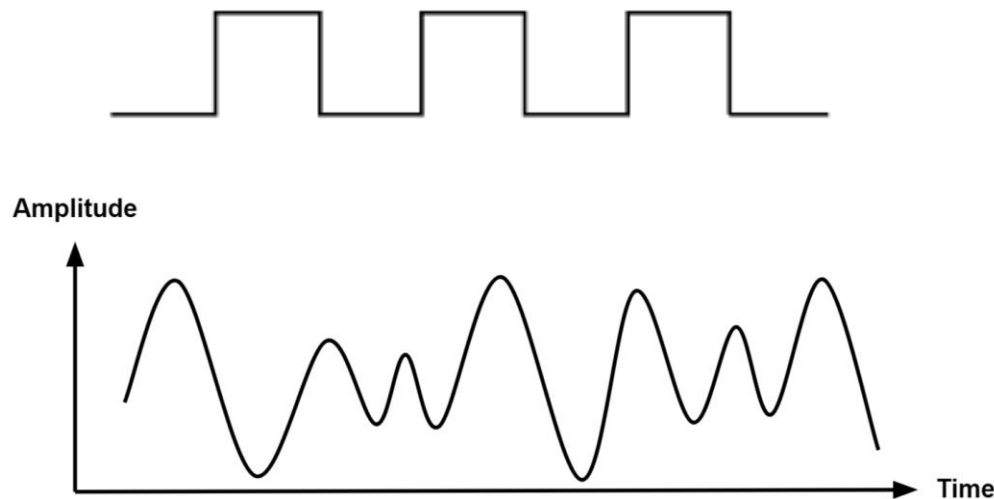
# High-Frequency Signals

## Definition

**Signals are merely useful, semi-periodic waveforms that we represent as changing voltage potentials or currents.**

**Examples include:**

- **Analog sensor outputs**
- **Digital communications**
- **Radio signals**
- **Output of an on/off switch**



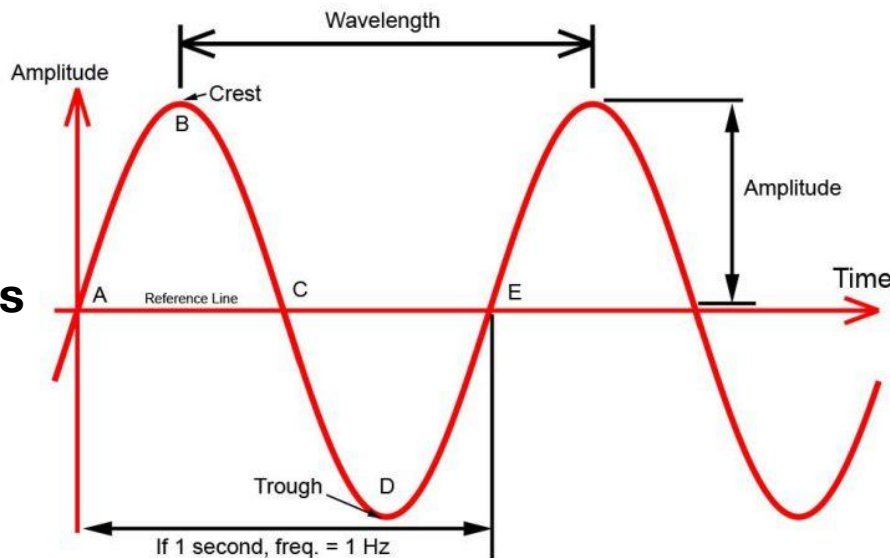
<https://www.monolithicpower.com/en/analog-vs-digital-signal>

# High-Frequency Signals

## Definition

For simplicity, we can represent all signals as simple sinusoidal waves of current that produce electric and magnetic fields on our PCB

(Fourier decomposition allows us to do this)



# High-Frequency Routing

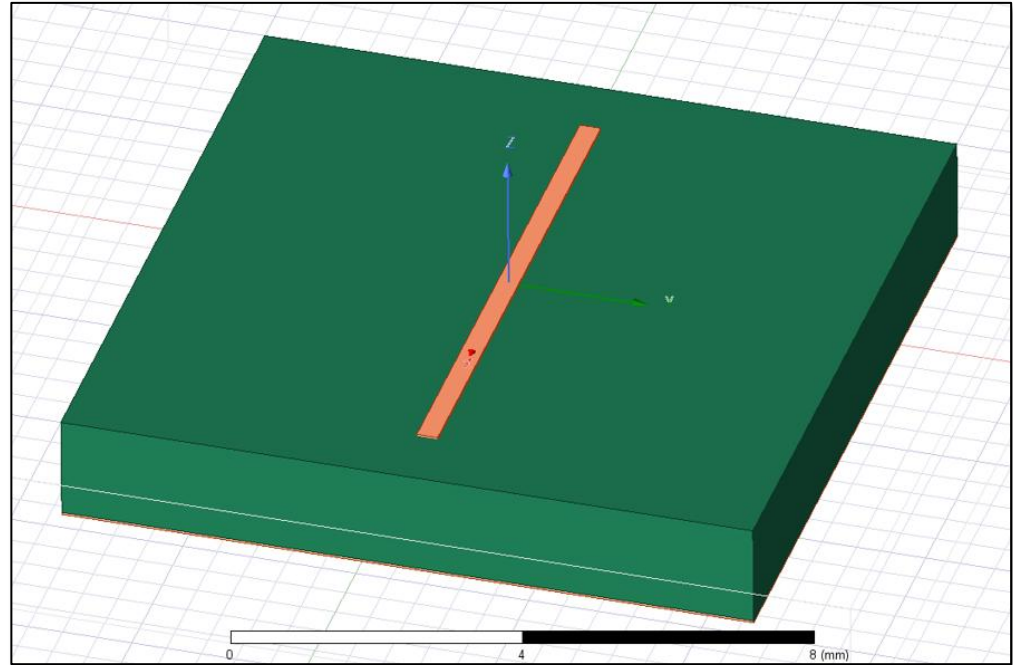
## Microstrip

Using Ansys HFSS to analyze how high-frequency signals are affected by PCB design elements

Taking a look at a microstrip model, consists of:

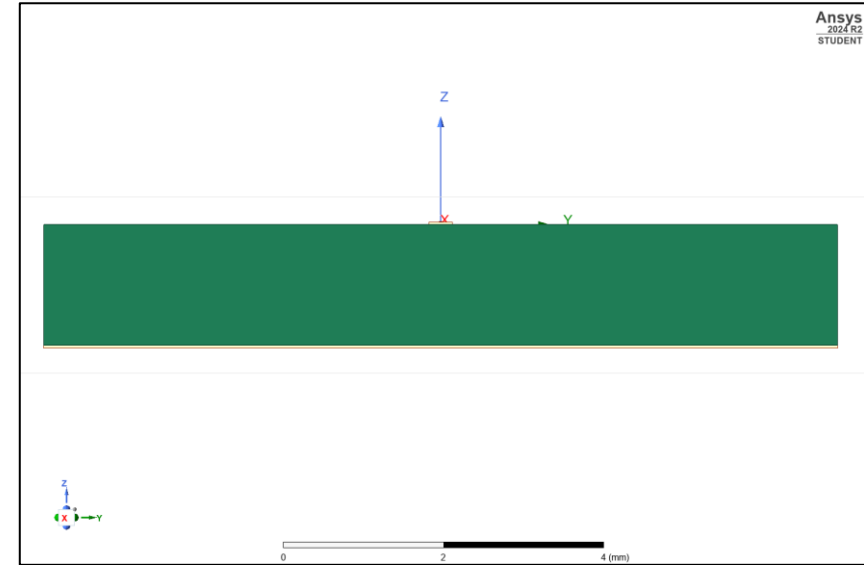
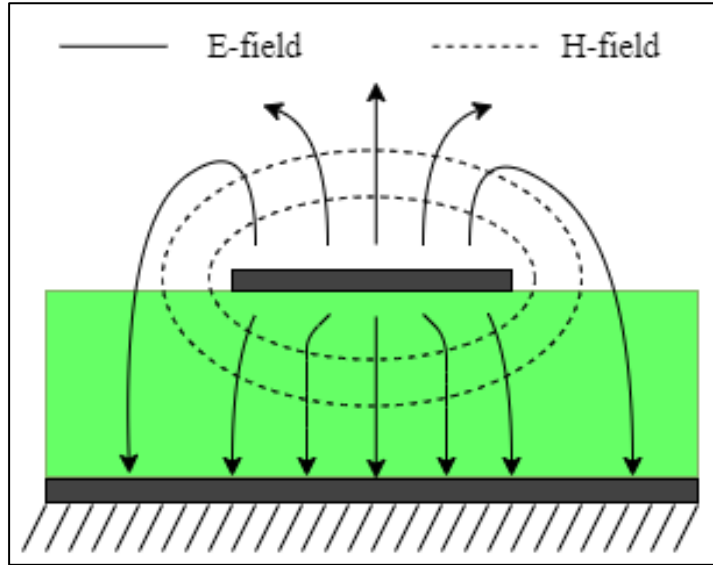
- Copper trace
- Dielectric (FR408HR used)
- Copper ground plane

Lumped element ports are attached to either end of the trace



# High-Frequency Routing

## Microstrip



<https://www.signalintegrityjournal.com/articles/2378-measuring-the-bulk-dielectric-constant-dk-on-a-microstrip-with-a-tdr>

# High-Frequency Routing

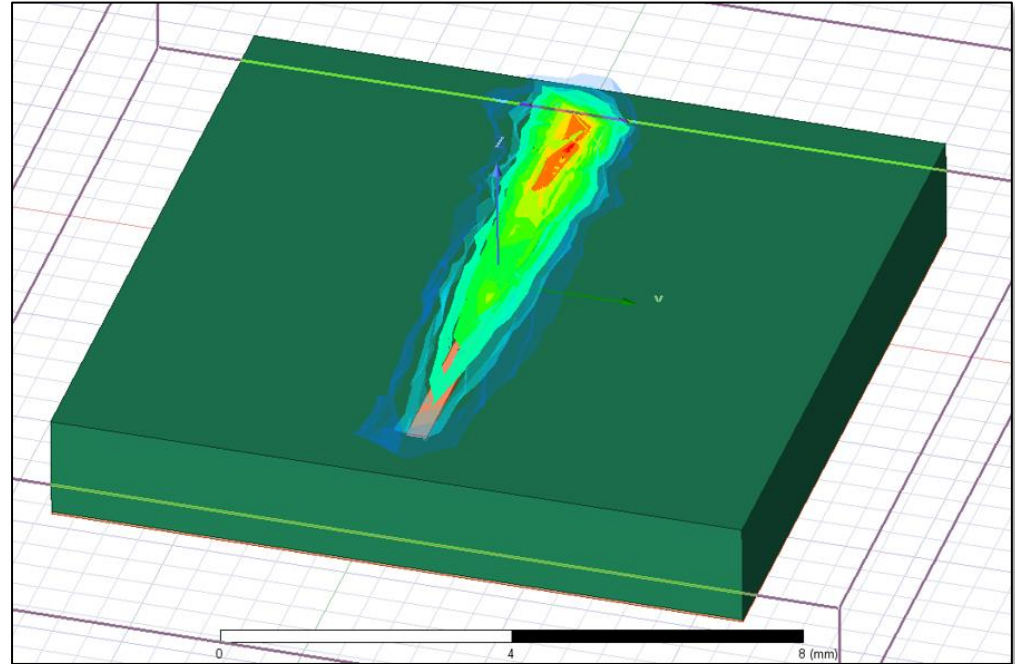
## Microstrip

Electric fields radiate around trace

We can inject high-frequency signals on either end/port on the trace and measure how they are affected:

- Signal degradation
- Coupling
- Radiation
- Reflections

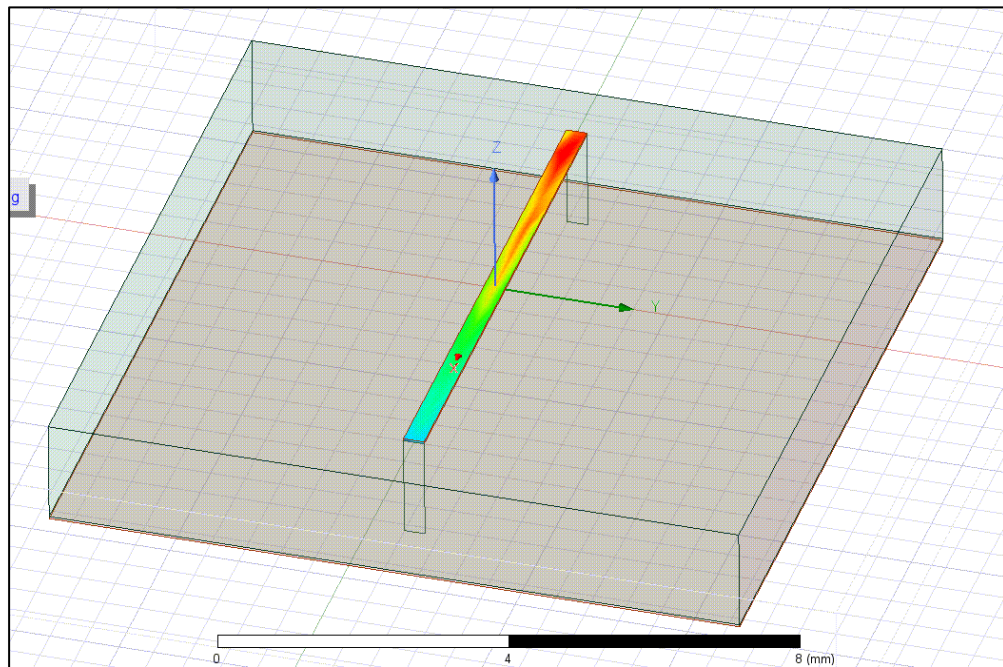
Able to visualize electric fields throughout materials (analogous to the current flow)



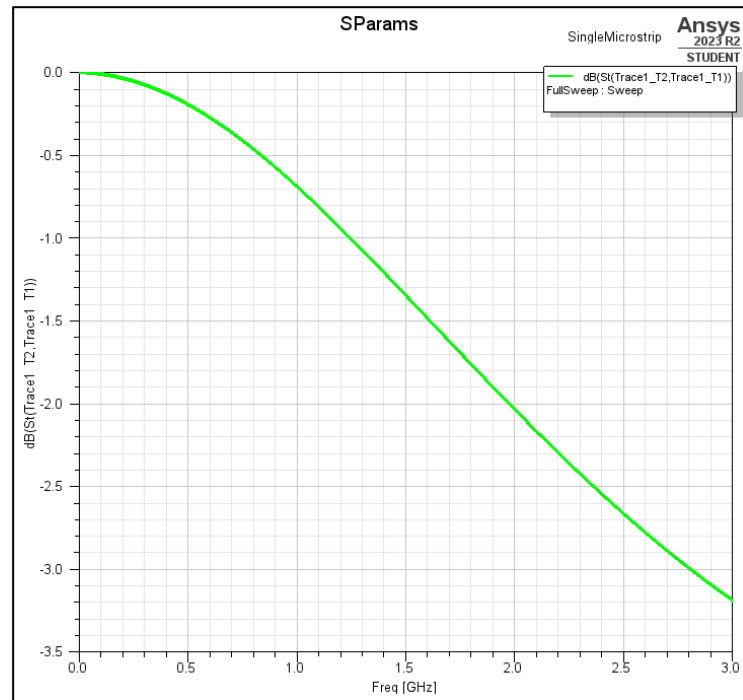
# High-Frequency Routing

## Microstrip

Electric field plotted on trace (2.4GHz source)



## Signal Loss (dB) vs. Frequency



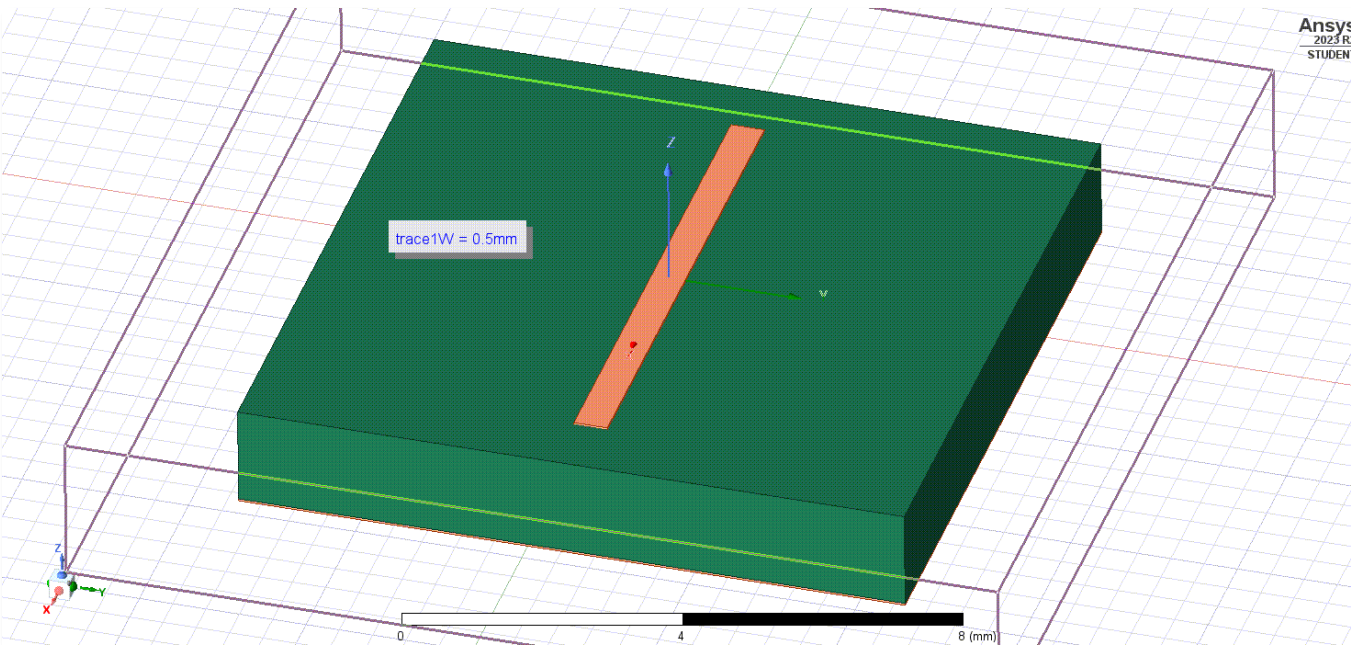


# High-Frequency Routing

## Impedance Matching

For a microstrip, impedance can be adjusted by changing the trace width.

The ports are  $50\Omega$  terminated. Matching the trace impedance close to  $50\Omega$  will result in lower loss.



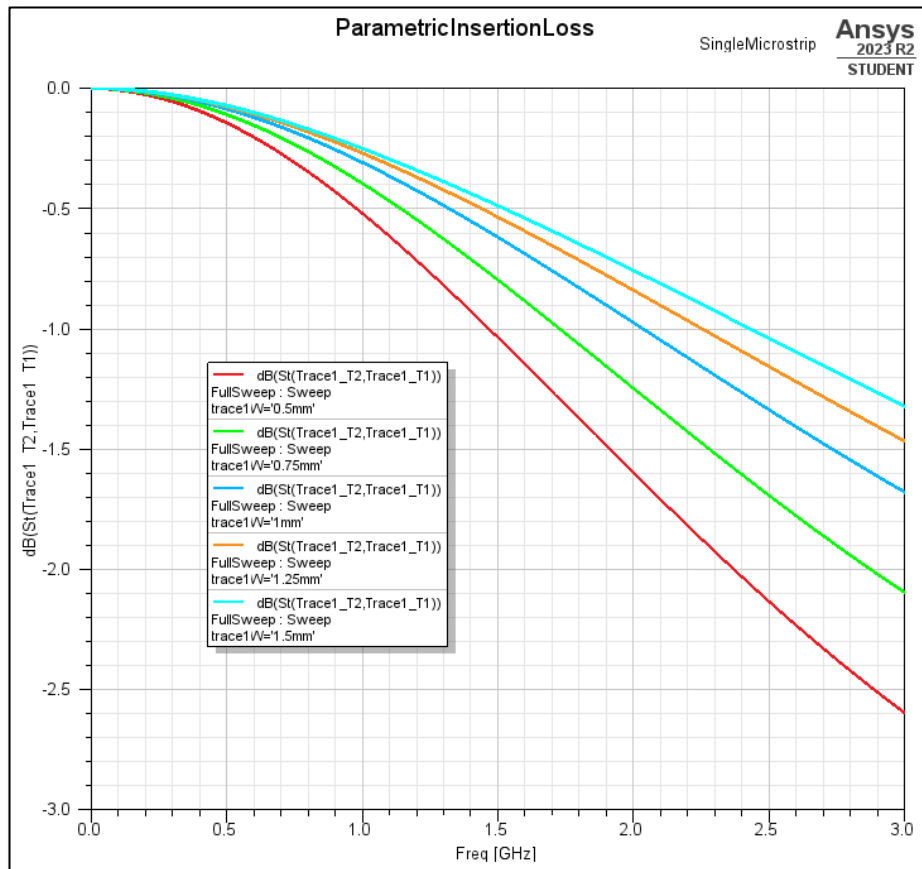
# High-Frequency Routing

## Impedance Matching

The currently modelled trace has a very high impedance ( $>50\Omega$ ). Therefore, widening it provides a better impedance match.

Impedance characteristics for a microstrip are affected by:

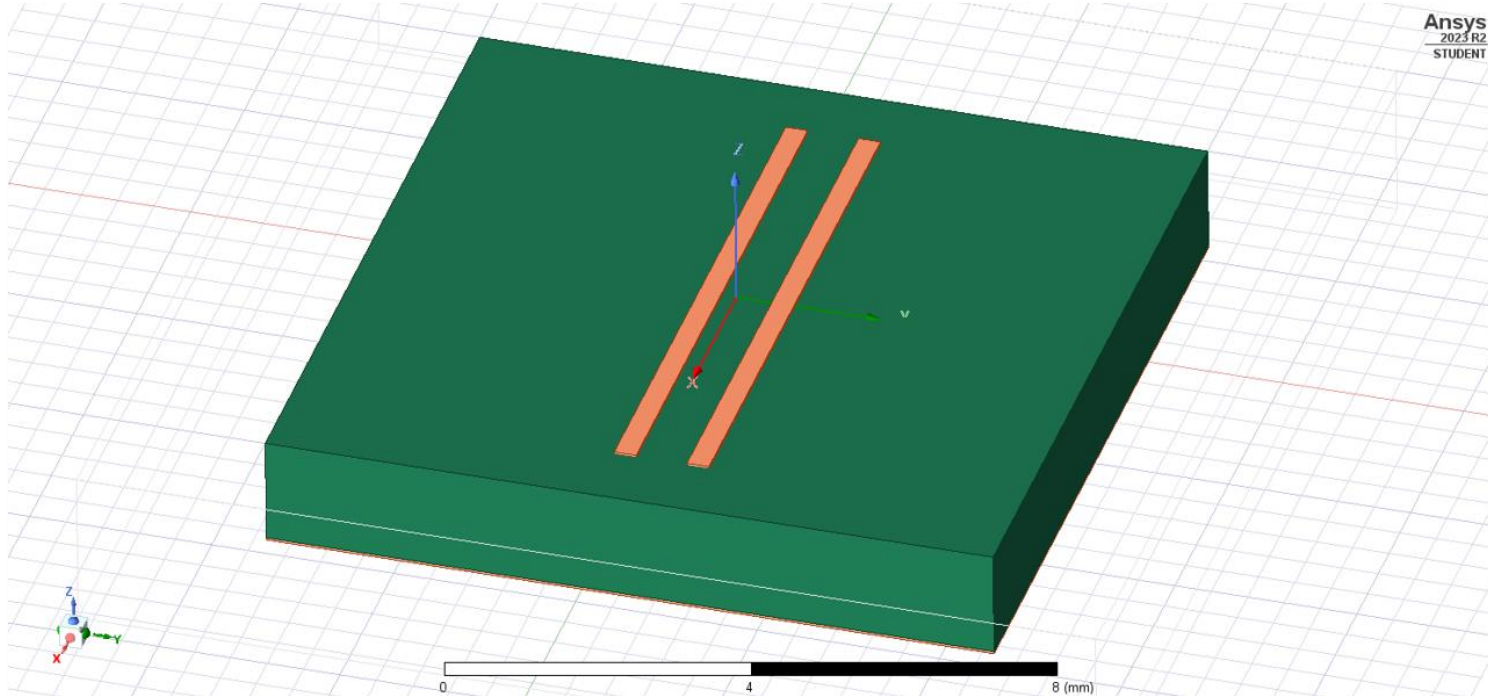
- Trace width
- Trace thickness
- Dielectric height
- Dielectric Constant ( $D_k$ ,  $E_r$ )



# High-Frequency Routing

## Coupling

What happens if we put another trace in parallel?



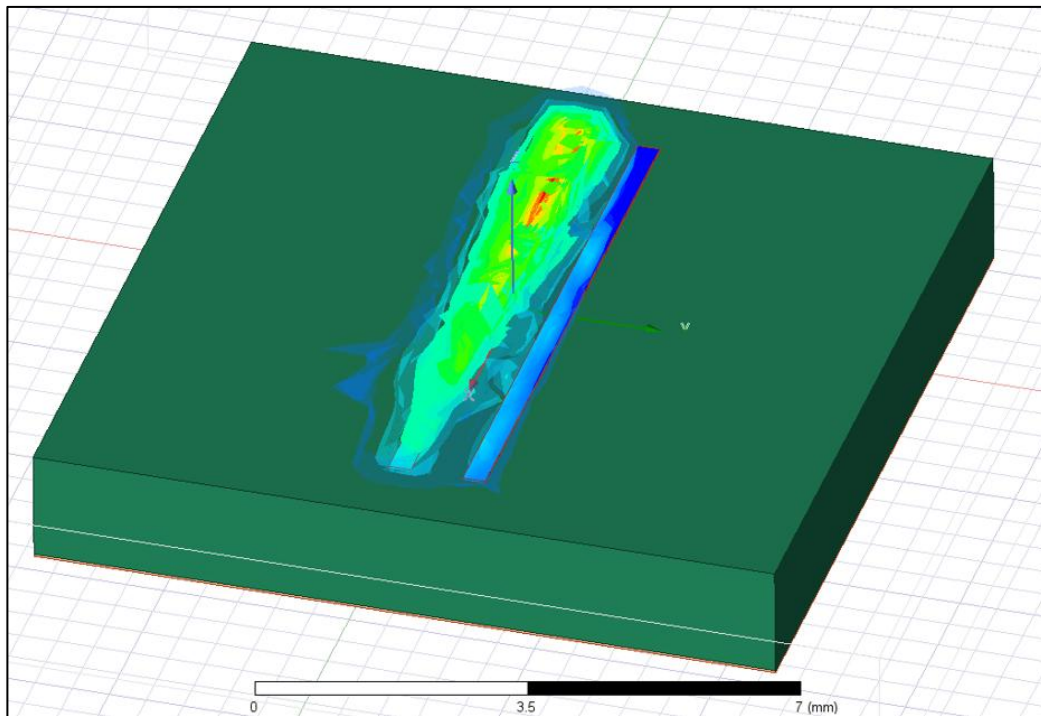
# High-Frequency Routing

## Coupling

**Notice how the electric fields propagating through the air around the excited (left) trace reaches the parallel (right) trace and induces internal fields**

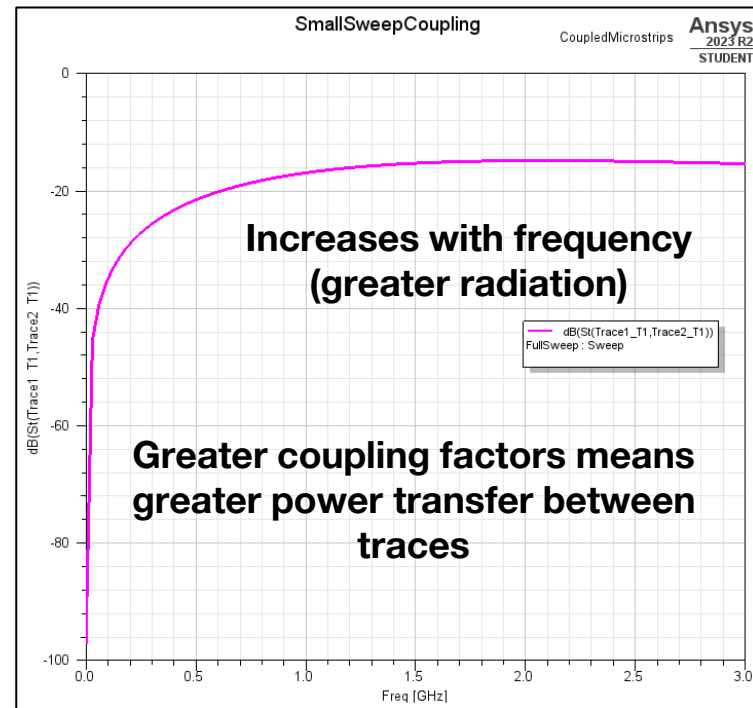
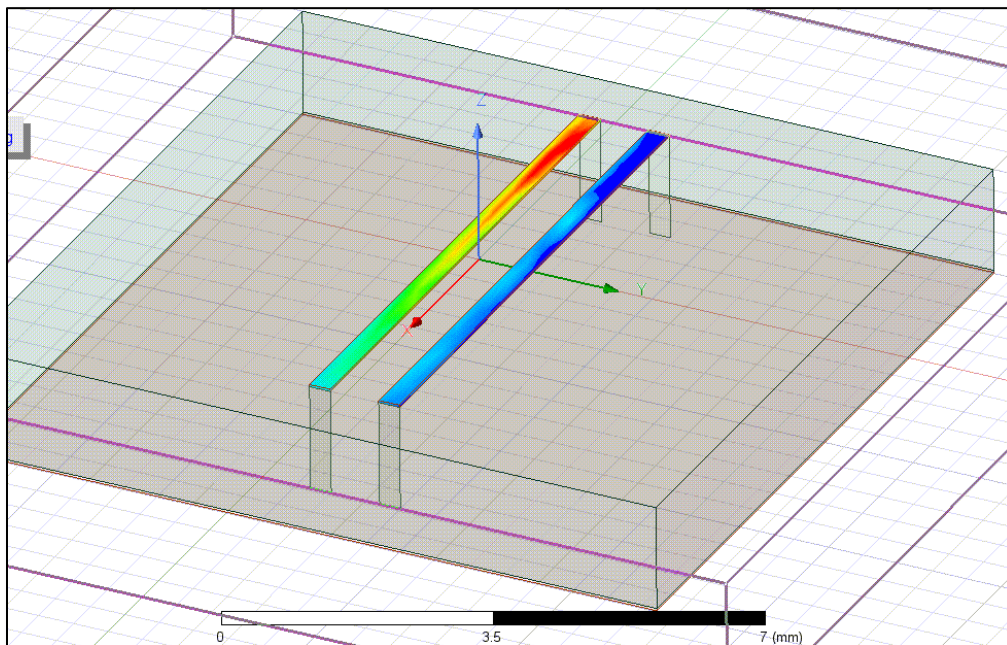
**A smaller, measurable copy of the signal is being coupled to the other trace**

**This can become a big issue for sensitive systems**



# High-Frequency Routing

## Coupling





# High-Frequency Routing

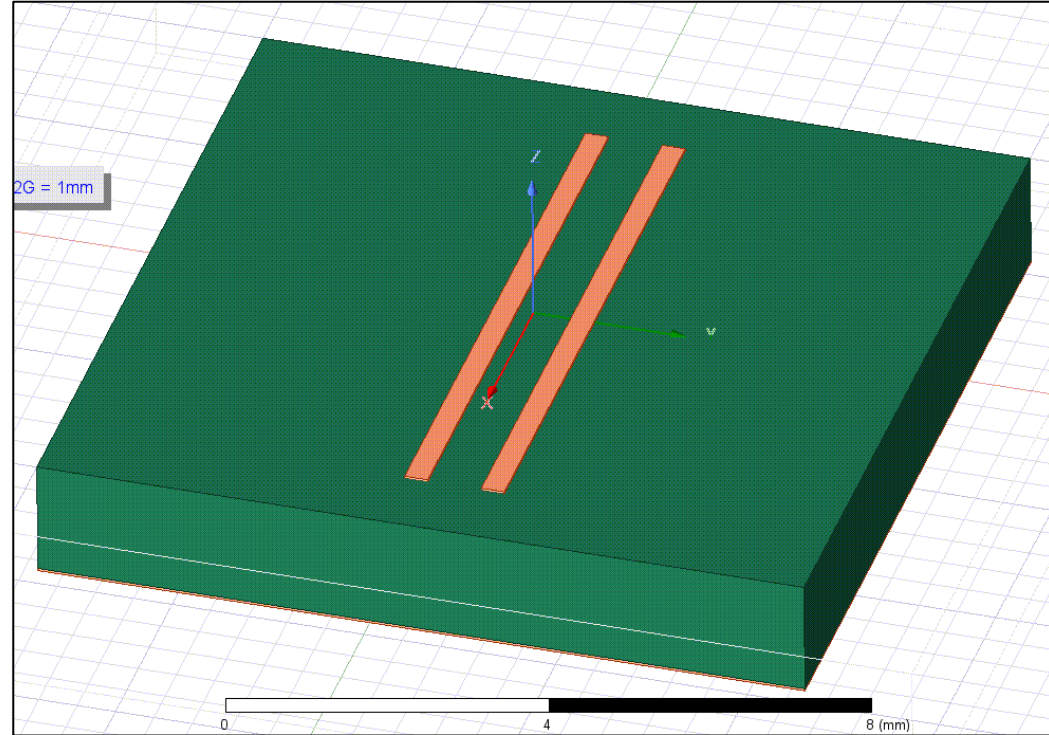
## Mitigating Coupling

**Coupling can adversely affect our signals.**

**At best, the coupled signals increase noise in our signal. At worse, they appear as valid signals at a receiving device (crosstalk)**

**We can reduce coupling by avoiding parallel signal traces (i.e., have them cross perpendicularly on different layers)**

**Increasing the separation between traces can also help**



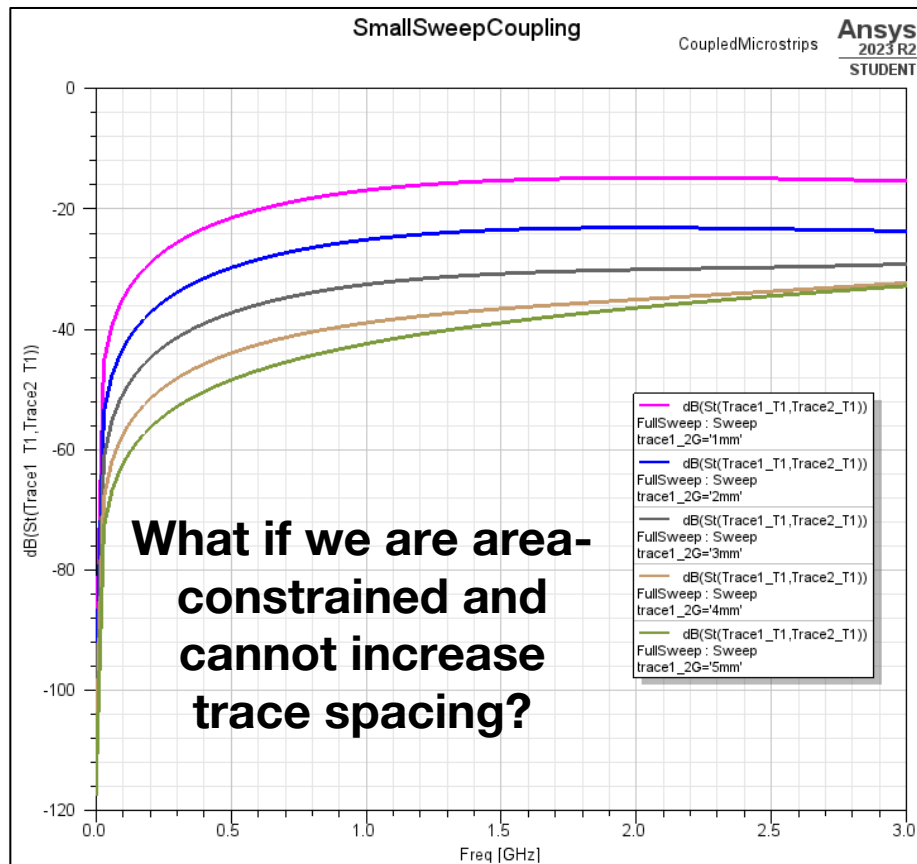
# High-Frequency Routing

## Mitigating Coupling

Increasing the distance between parallel traces will weaken coupling fields (inversely proportional to distance)

For differential traces, this coupling is utilized to maintain a particular differential impedance

- Ensure to follow impedance requirements for differential signal trace pairs



1 mm

2 mm

3 mm

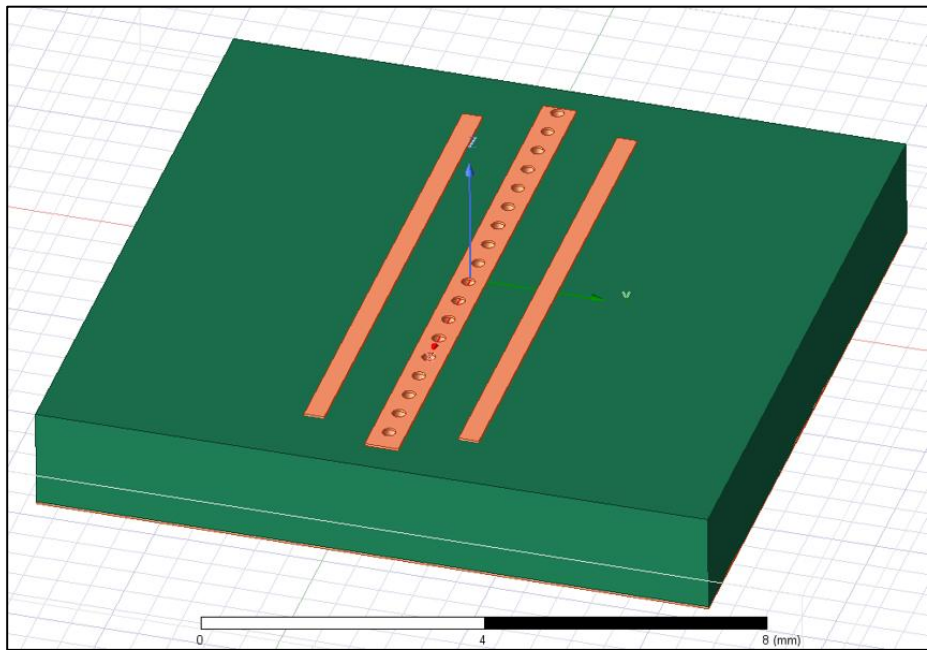
4 mm

5 mm

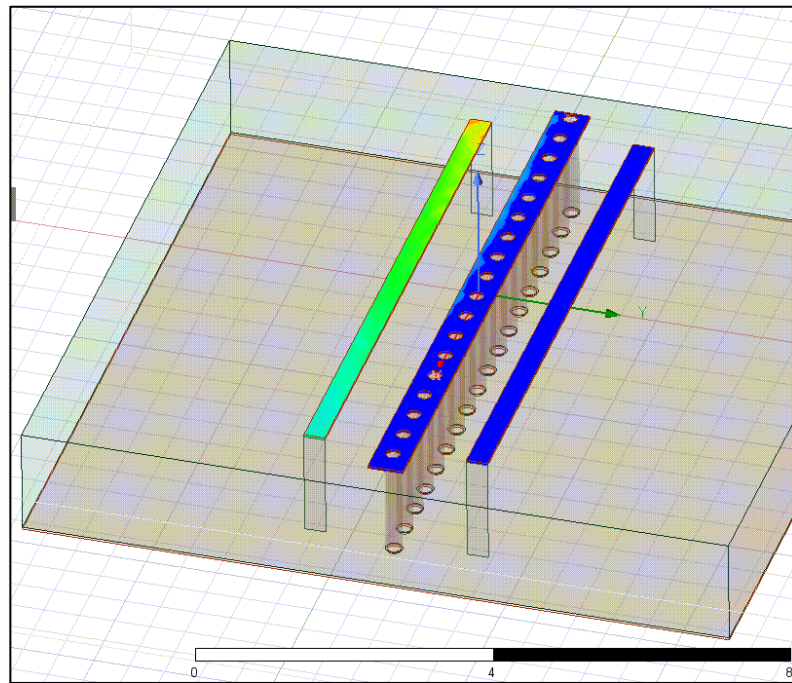
# High-Frequency Routing

## Mitigating Coupling

Add a ground trace/pour/via-fence between



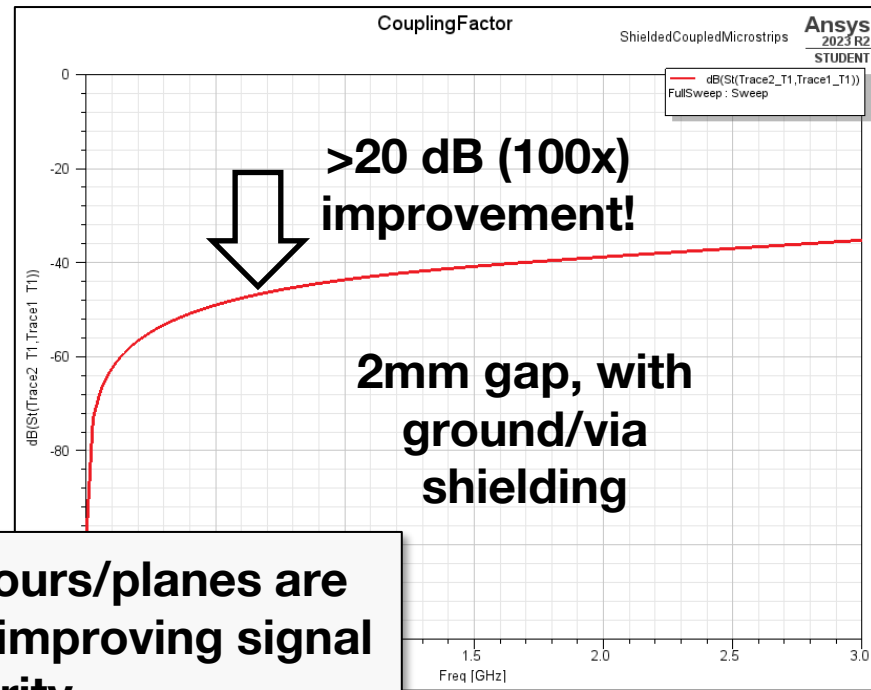
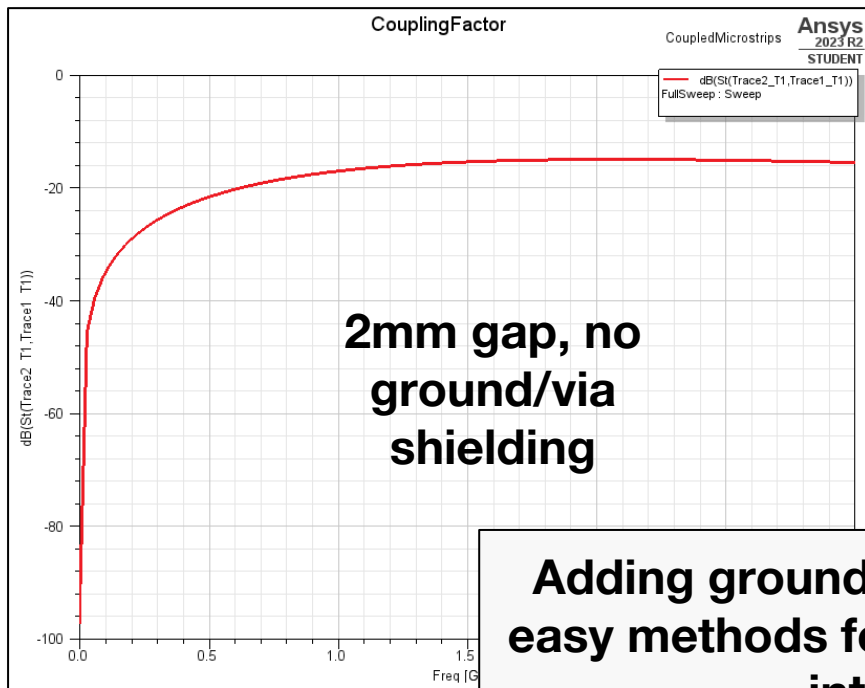
Radiated fields couple to the  
return path (GND)





# High-Frequency Routing

## Mitigating Coupling



Adding ground pours/planes are easy methods for improving signal integrity

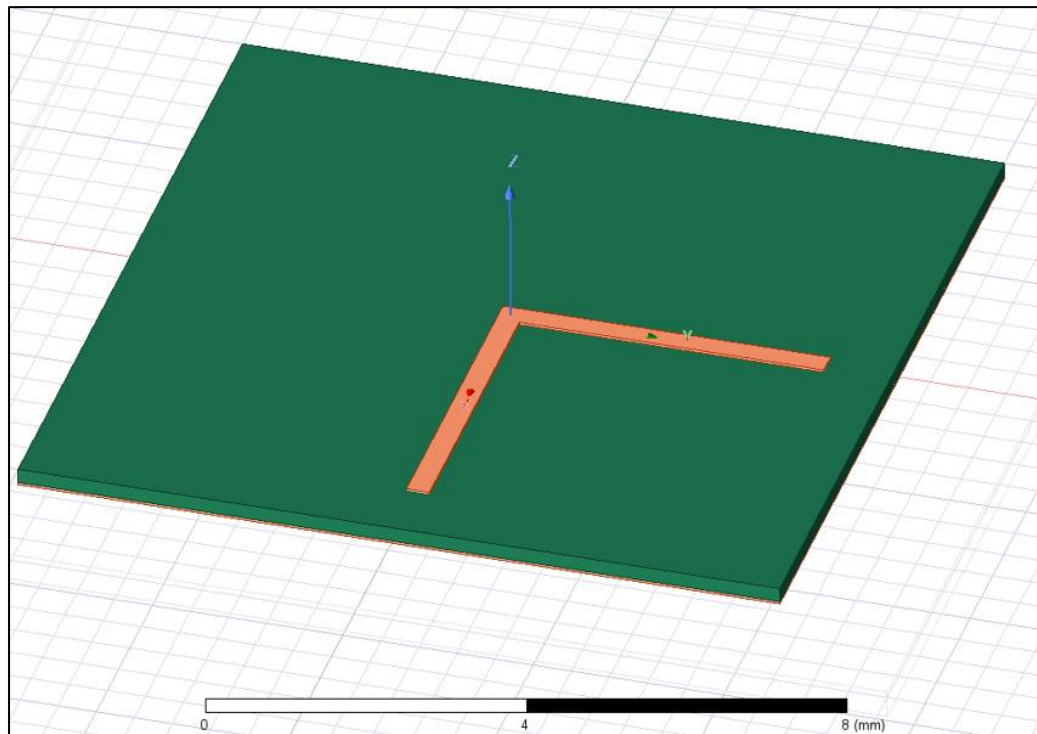
# High-Frequency Routing

## Microstrip Bends

**Impedance mismatches can occur at abrupt discontinuities in a trace, such as sharp (90 degree) bends**

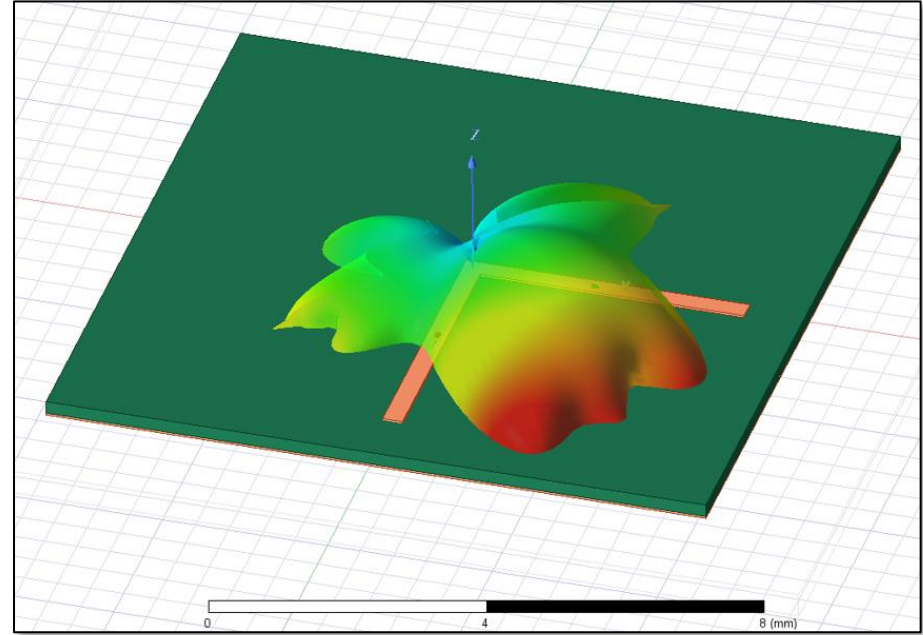
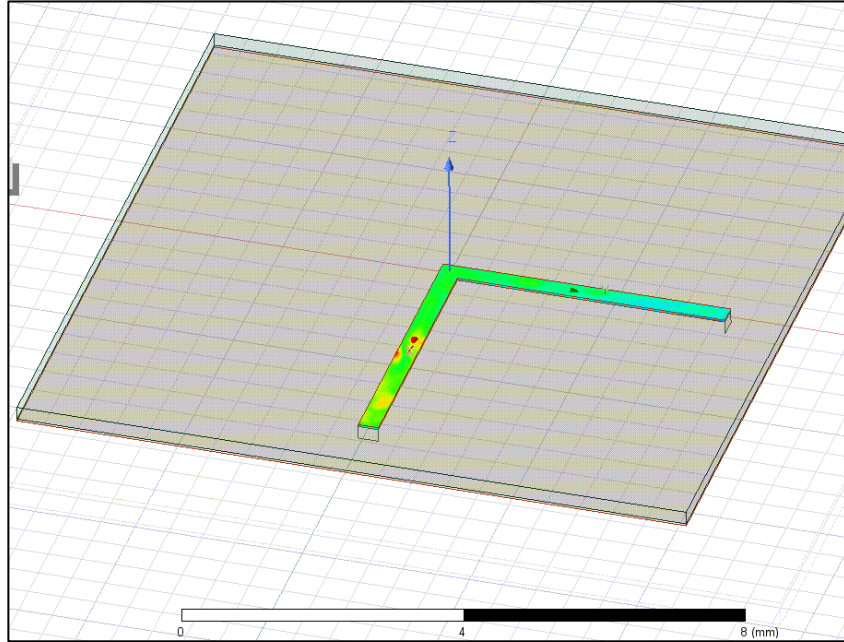
**The bend itself can resonate and have its own (different) impedance from the rest of the microstrip**

**The result is signal reflections, radiation, and degradations!**



# High-Frequency Routing

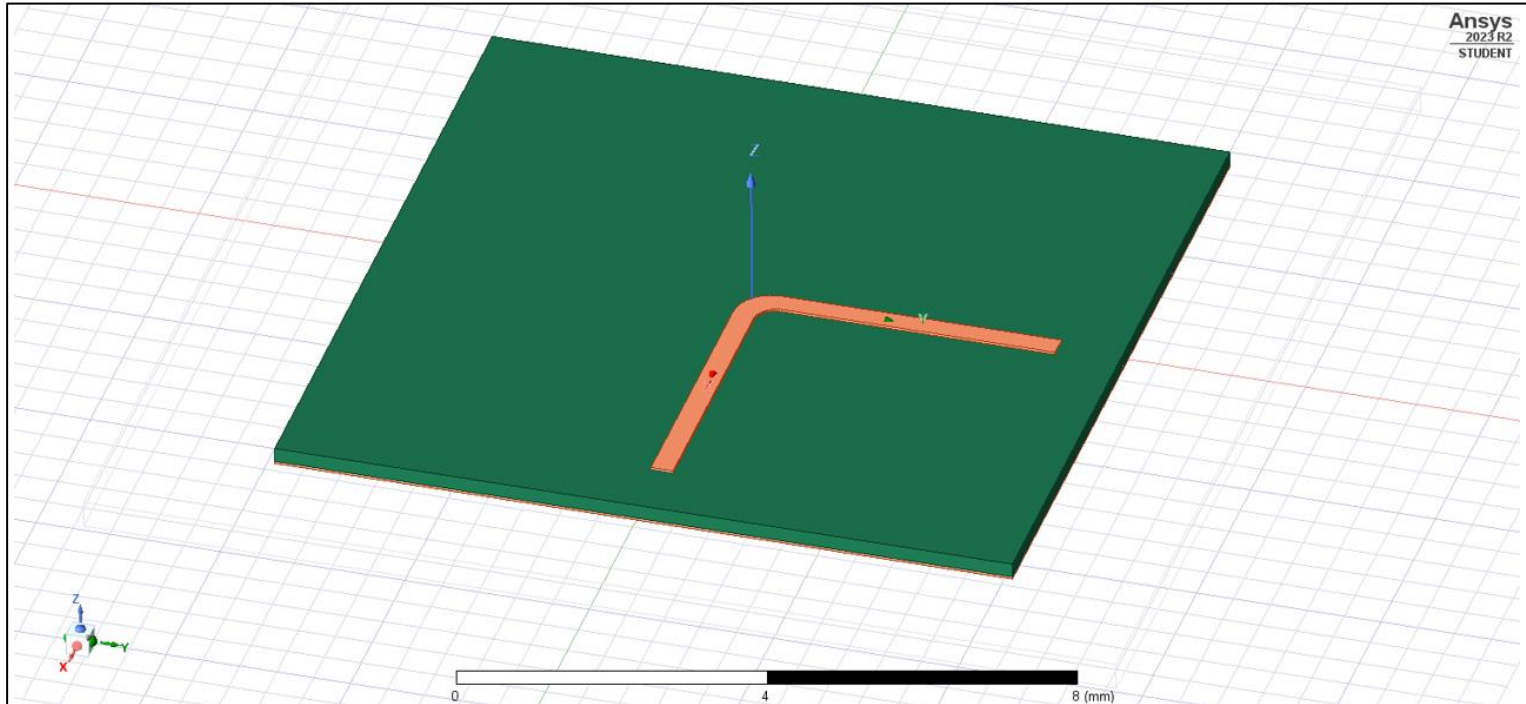
## Microstrip bends



# High-Frequency Routing

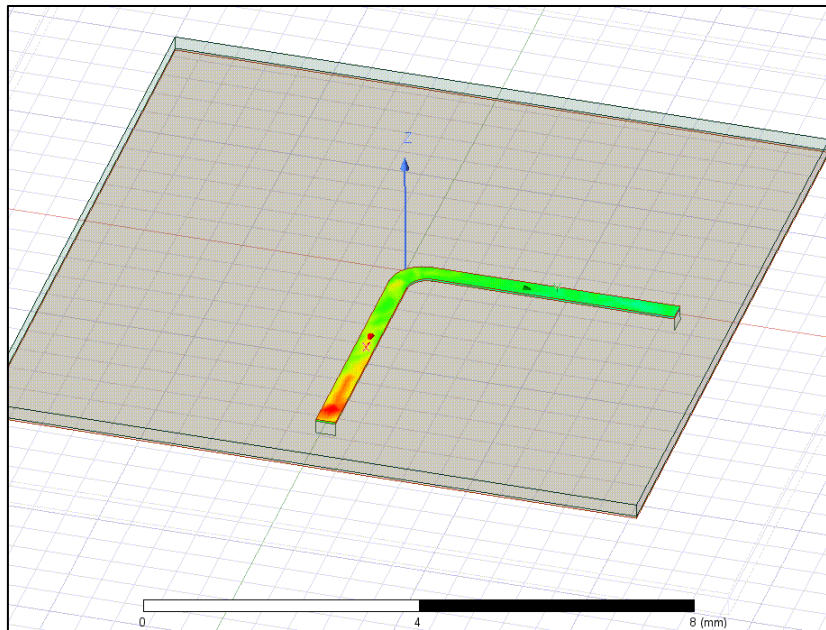
## Microstrip Bends

**Solution: smooth, wide bends**

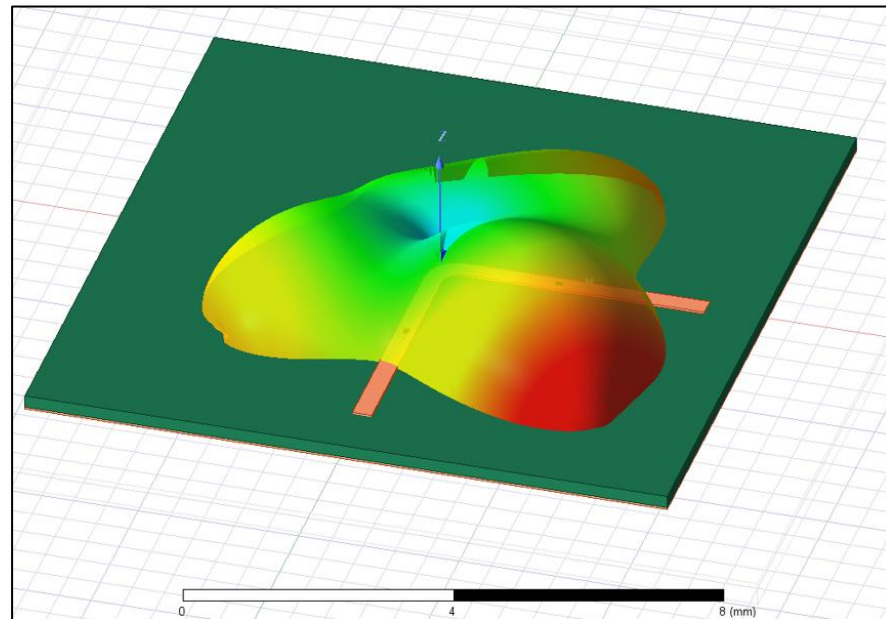


# High-Frequency Routing

## Microstrip Bends



**Even field distribution throughout bend**

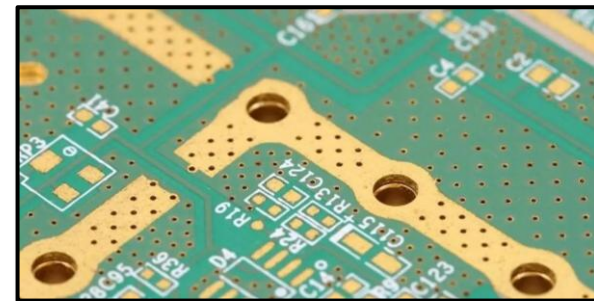
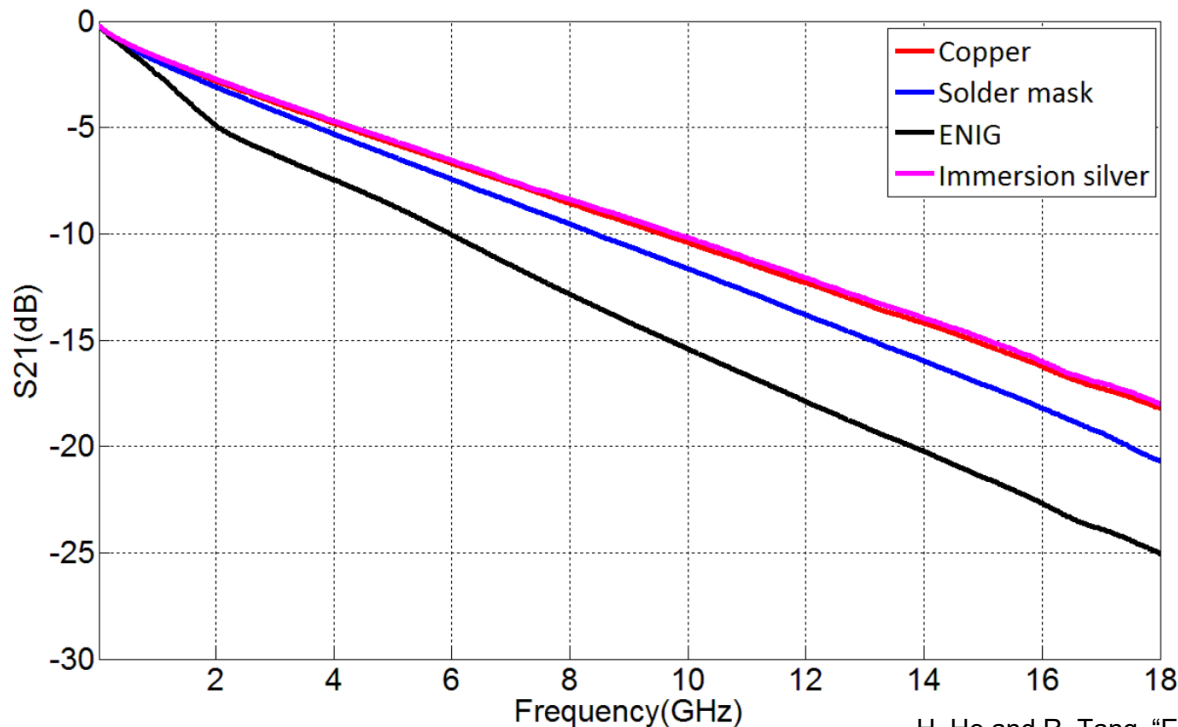


**Smooth, weaker near-field radiation patterns**



# High-Frequency Fabrication

## Surface Finish



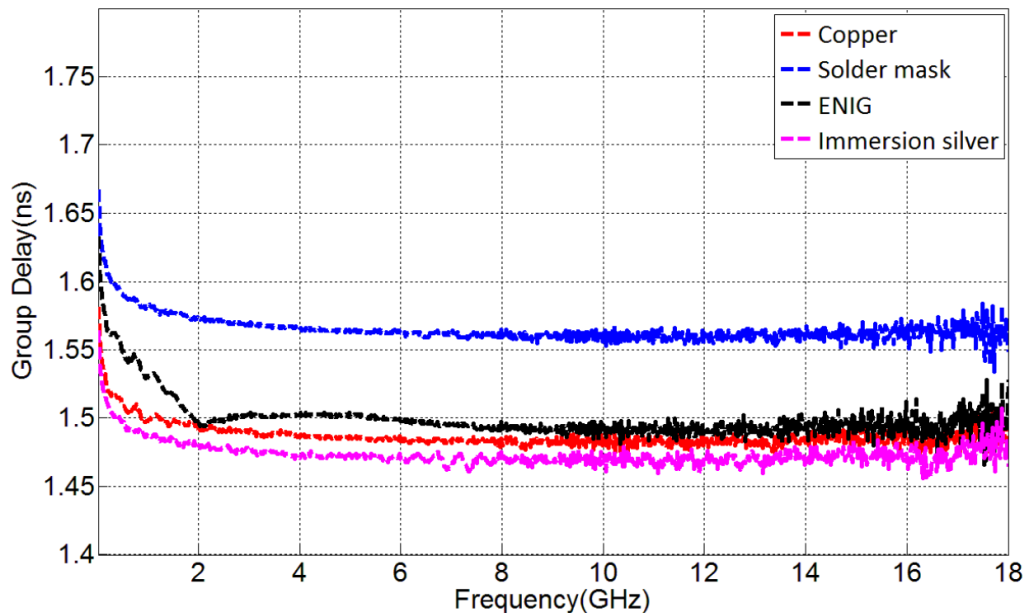
**Soldermask → dielectric  
causes dissipation**

**Metal surface finishes →  
conductor losses**

H. He and R. Tang, "Effect of Permittivity and Dissipation Factor of Solder Mask upon Measured Loss," Las Vegas, Mar. 2016.

# High-Frequency Fabrication

## Surface Finish



**Soldermask adds additional permittivity → expect greater group delay**

**ENIG contains large nickel layer → nickel has high permeability at low frequencies → expect varying group delay**

**Figure 6 - S21 and delay measurements for 8.265 inch traces with different surface finishes**  
(above: S21; below: group delay )

H. He and R. Tang, "Effect of Permittivity and Dissipation Factor of Solder Mask upon Measured Loss," Las Vegas, Mar. 2016.

# High-Frequency Fabrication

## Surface Finish

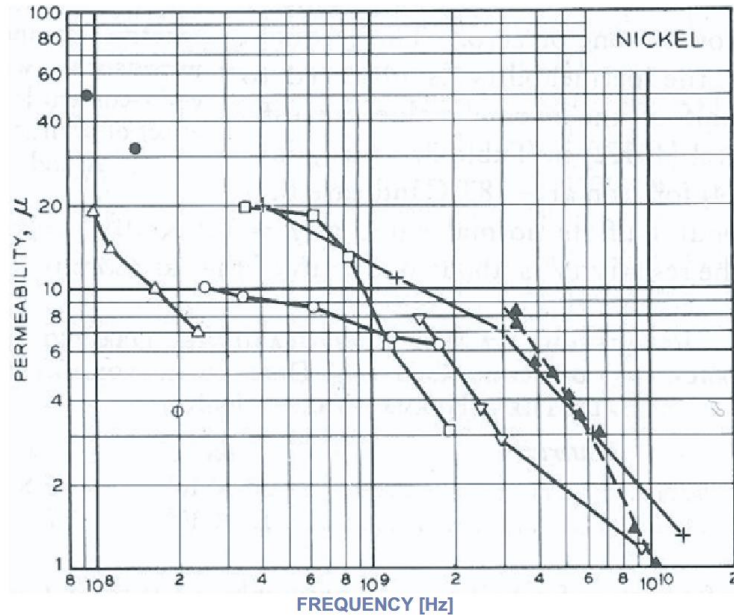


Figure 1: Measured frequency characteristics of initial permeability for nickel [10].

(+ Arkadiew [11], ∇ Simon [12], ▲ Hodsman et al. [13])

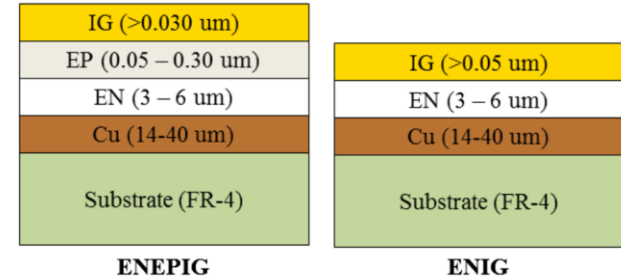


Fig. 2. Schematic of layer configurations of ENEPIG, ENIG, and Ni/Au board finishes.

M. Ratzker, A. Pearl, M. Osterman, M. Pecht, and G. Milad, "Review of Capabilities of the ENEPIG Surface Finish," J Electron Mater, vol. 43, no. 11, pp. 3885–3897, Nov. 2014, doi: 10.1007/s11664-014-3322-z.

$$\delta = \sqrt{\frac{2\rho}{\omega\mu}}$$

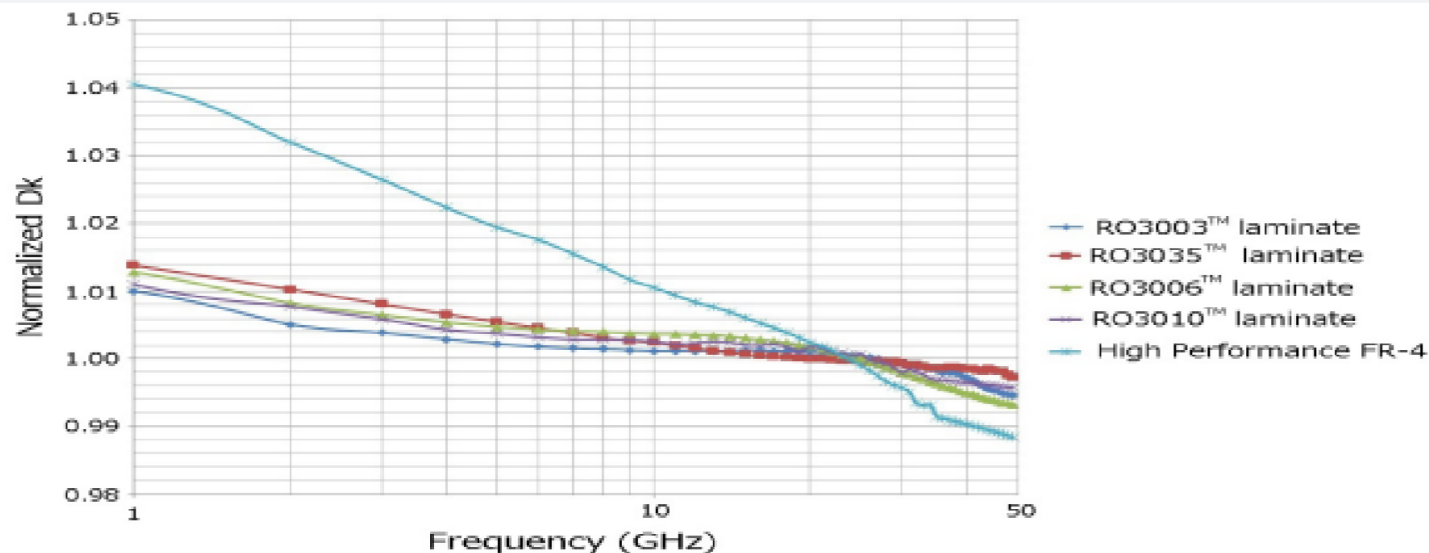
S. Lucyszyn, "Microwave Characterization of Nickel," PIERS Online, vol. 4, no. 6, pp. 686–690, 2008, doi: 10.2529/PIERS080119215655.



# High-Frequency Fabrication

## Substrate

**Chart 3:** Normalized Dk vs. Frequency using microstrip differential phase length method 50 ohm microstrip circuits based on ~20mil thick laminates

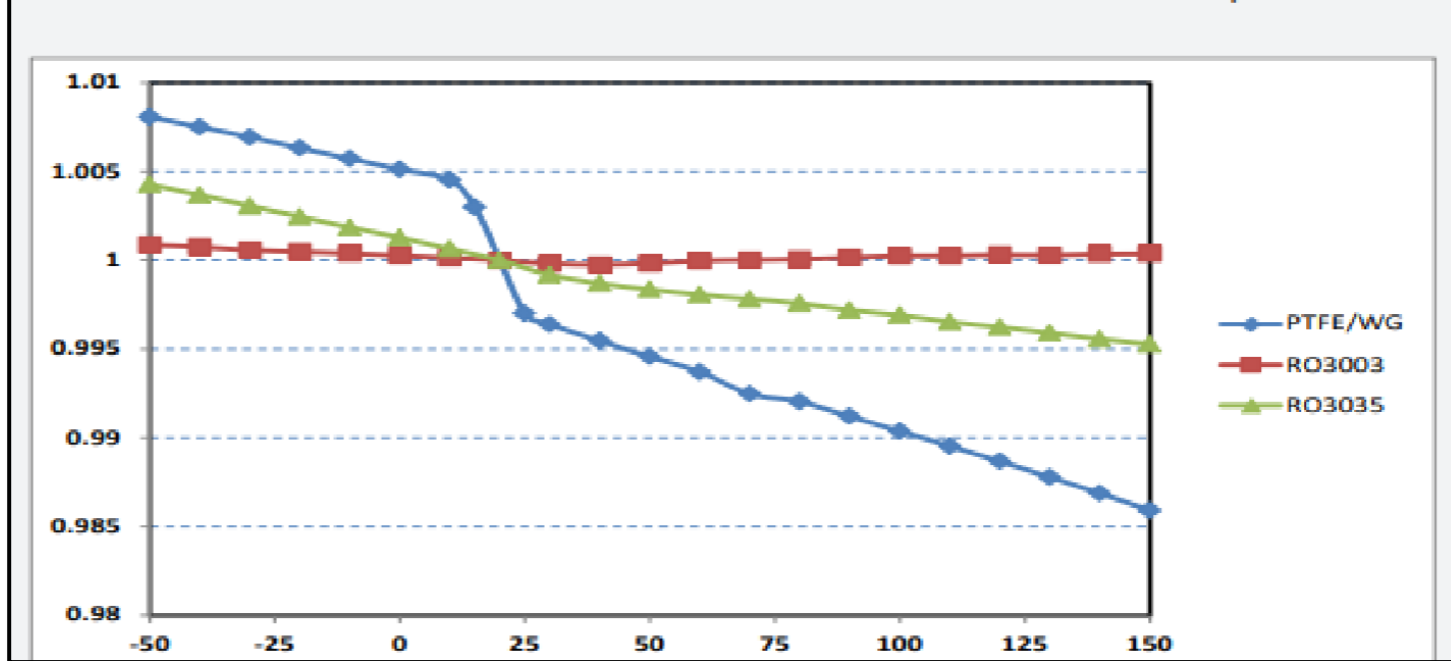


Rogers Corporation

# High-Frequency Fabrication

## Substrate

Chart 1: RO3003 and RO3035 Laminate Dielectric Constant vs. Temperature



Rogers Corporation

# High-Frequency Routing

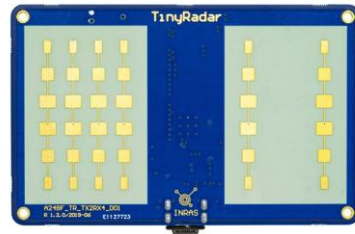
## Key Takeaways

- ❑ As signals reach greater frequencies, their wavelengths decrease, which results causes greater susceptibility to wave phenomenon and parasitic circuit elements
- ❑ Impedance mismatches between traces, discontinuities, and devices can lead to signal degradation, reflection, and radiation, which we can simulate
- ❑ Use appropriate high-frequency PCB structures (e.g., microstrip, coplanar waveguide) when impedance matching is needed
- ❑ Close, parallel traces can couple to one another, use appropriate spacing, ground pours, and via fences to reduce coupling
- ❑ Sharp trace turns can cause impedance mismatches, use smooth bends instead

# Examples

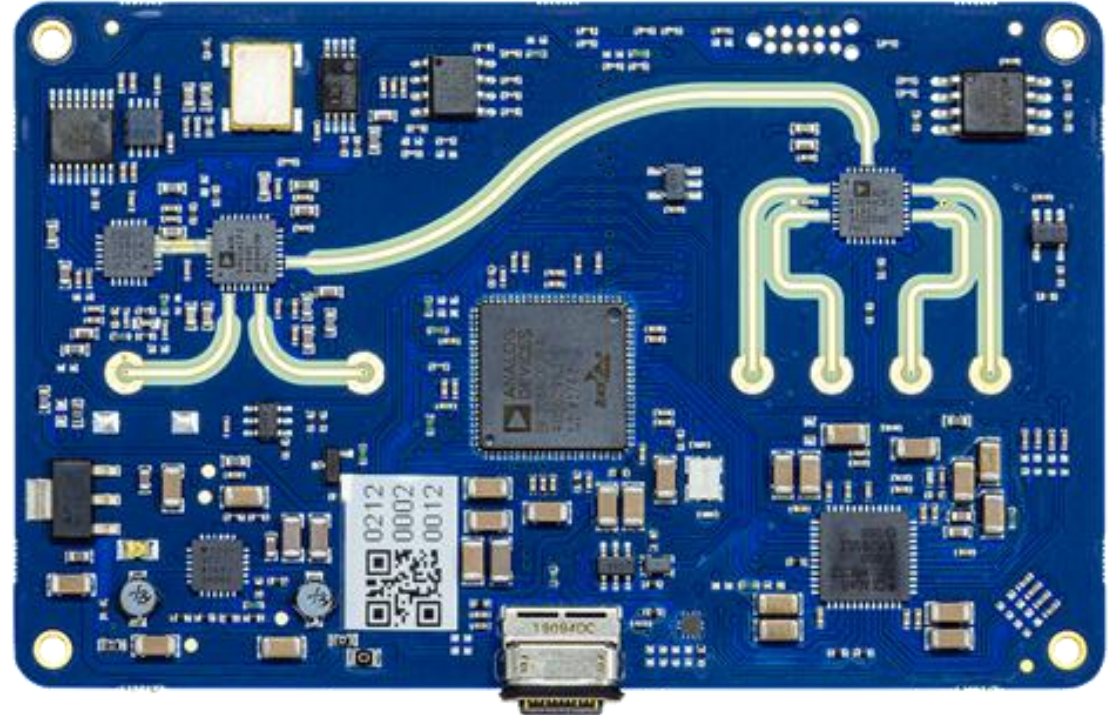
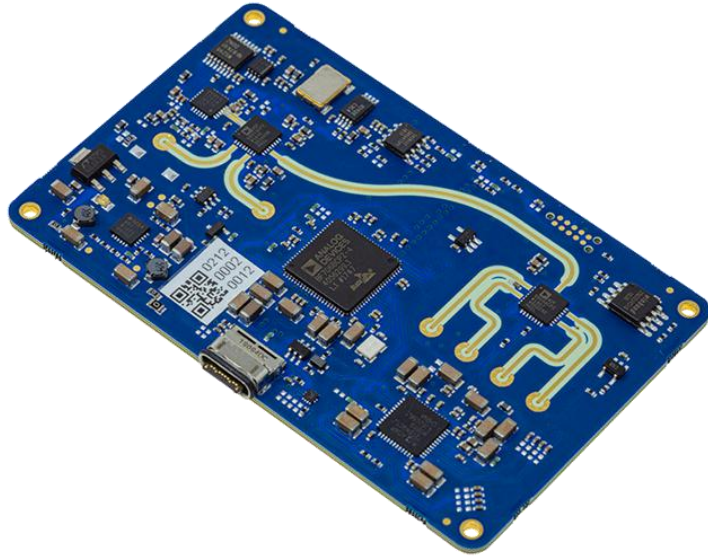
# Examples

## 24 GHz Radar



Phased  
Array!

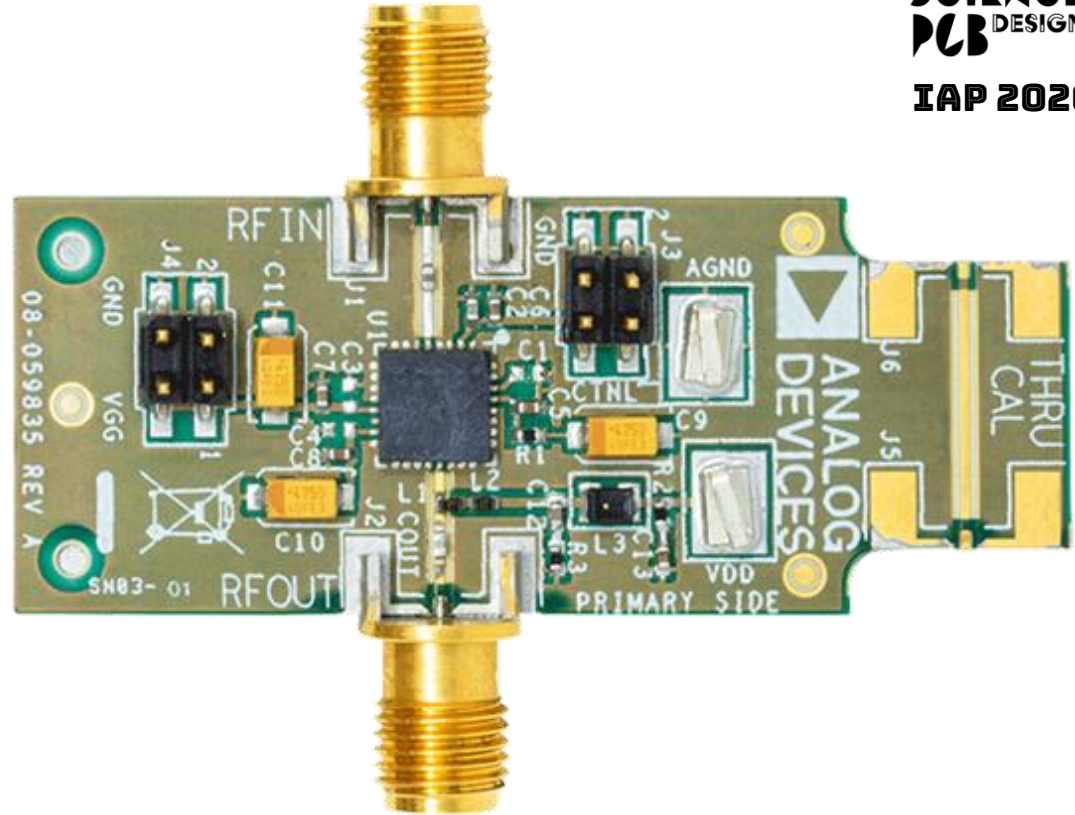
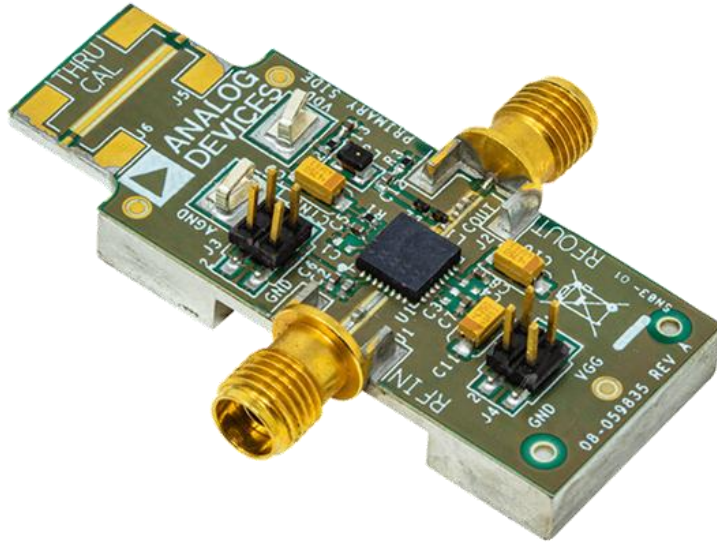
THE ART AND  
SCIENCE OF  
PCB DESIGN  
IAP 2026



<https://www.analog.com/en/design-center/evaluation-hardware-and-software/evaluation-boards-kits/eval-tinyrad.html#eb-overview>

# Examples

## 28 GHz Amplifier

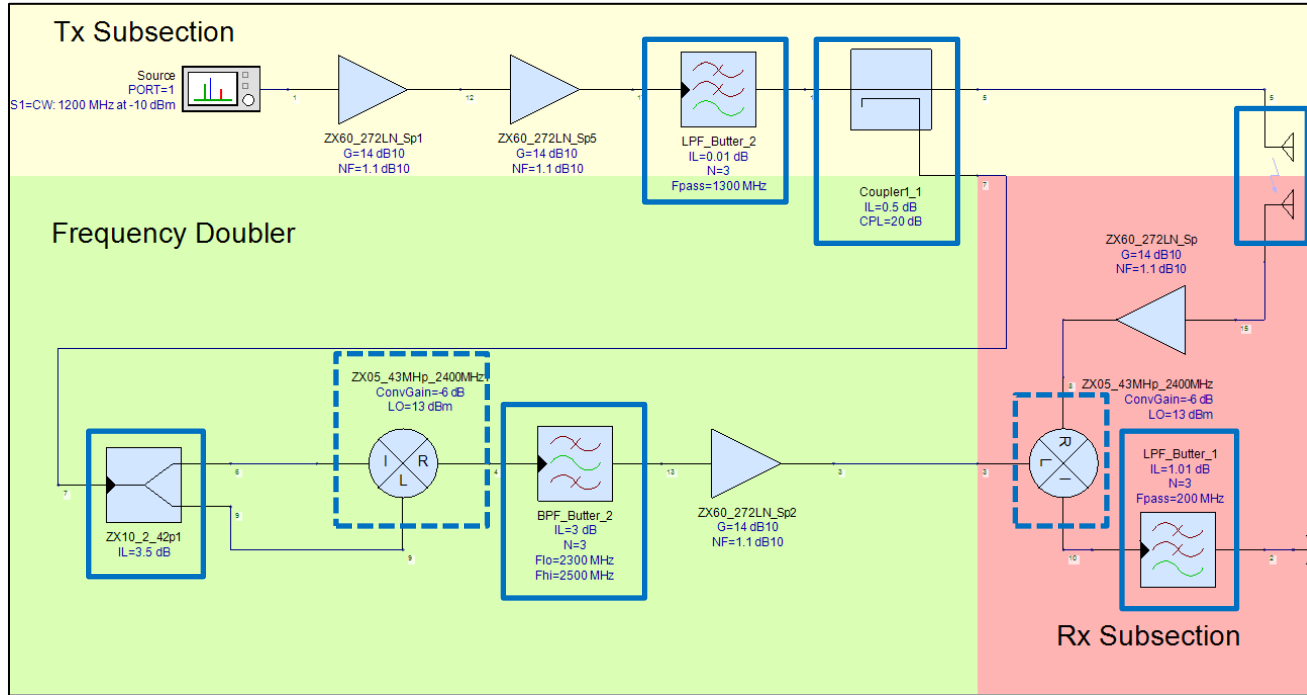


<https://www.analog.com/en/design-center/evaluation-hardware-and-software/evaluation-boards-kits/EVAL-HMC994APM5.html#eb-overview>

# Planar Microwave Devices

# Planar Microwave Devices

## RF Passive Components



**We can use PCBs to create passive microwave components**

**PCBs offer a cheaper medium for microwave device fabrication**

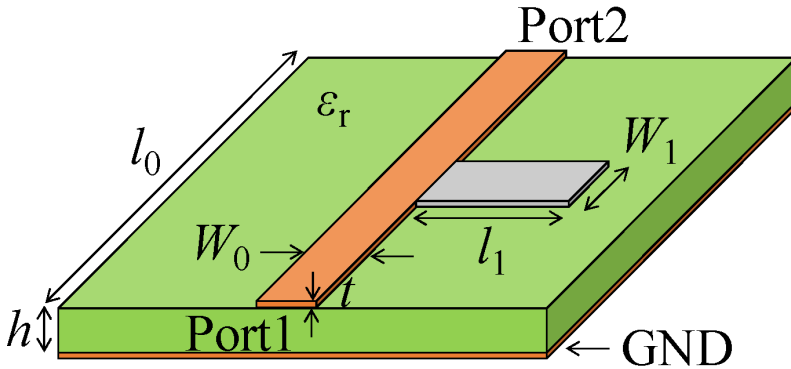
**Also allows for greater integration of an RF system onto a single board**



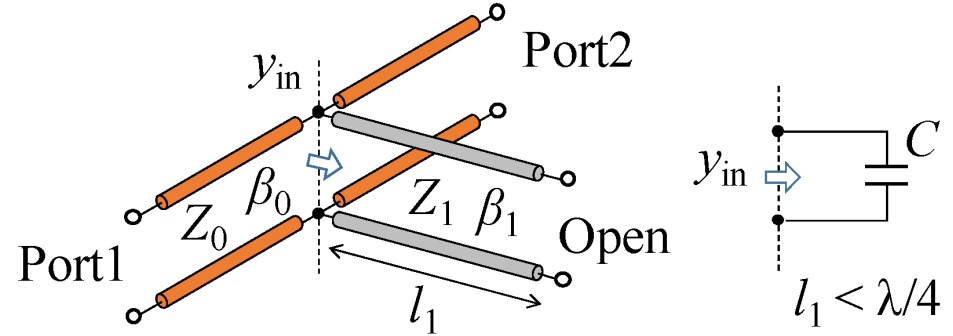
# Microstrip Resonators

## Open-Circuit Stub

A resonator can be created using a length of microstrip and a termination



(a)



(b)

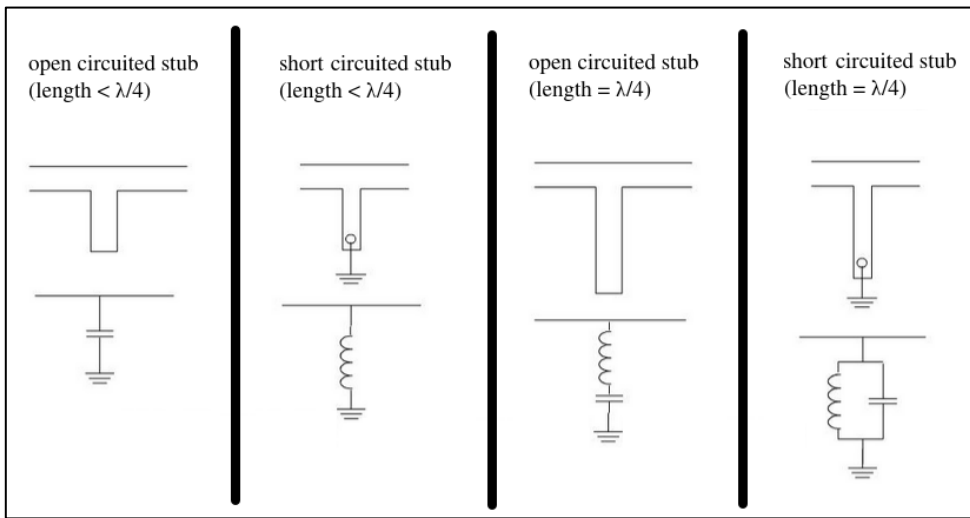
In this case, an open-circuit stub can be added

- Acts like a shunt capacitor when its length is small

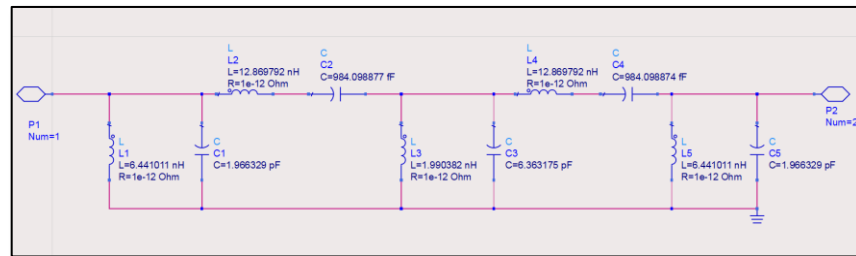
# Microstrip resonators

## Filters

Different stub lengths and terminations can create different LC combinations



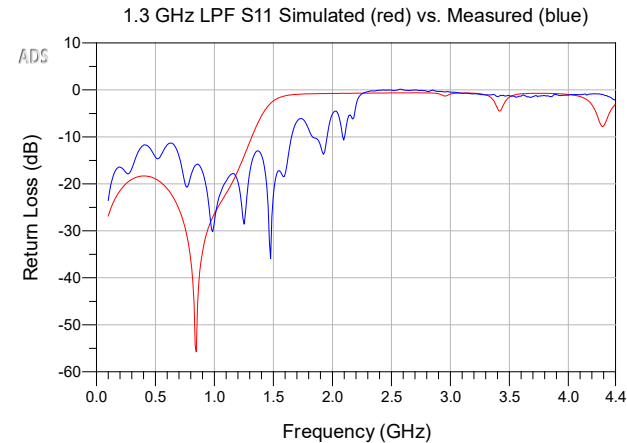
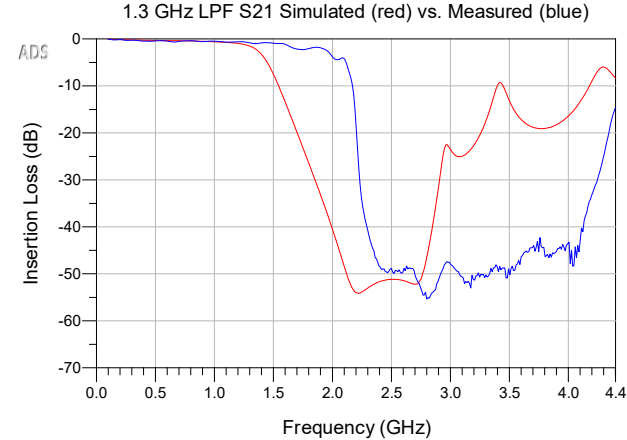
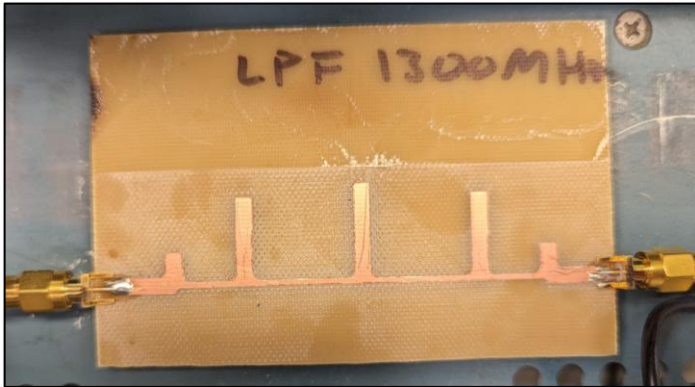
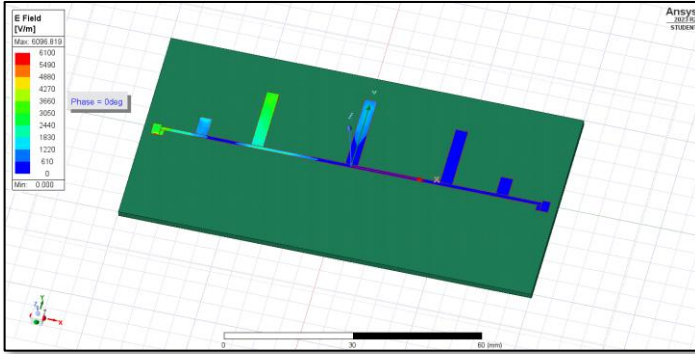
We can utilize this effect to create filters



<https://electronics.stackexchange.com/questions/460101/deriving-microstrip-stub-equations>

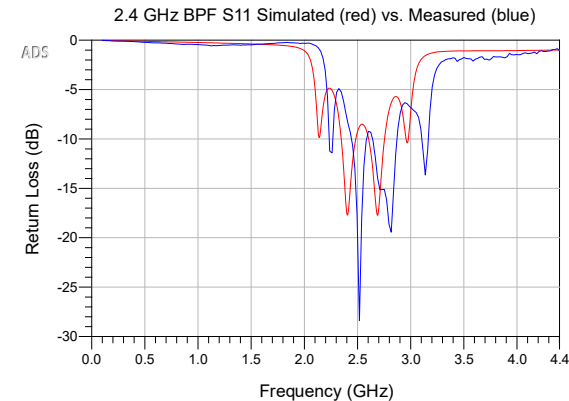
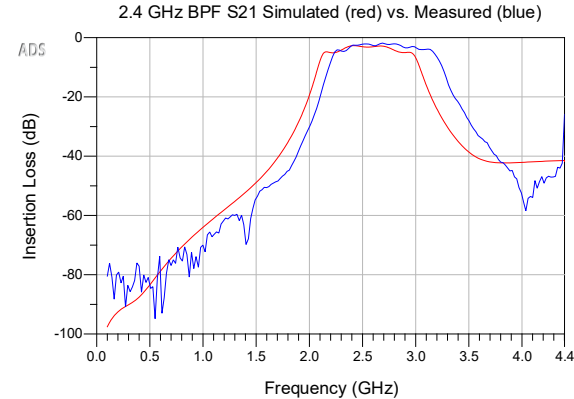
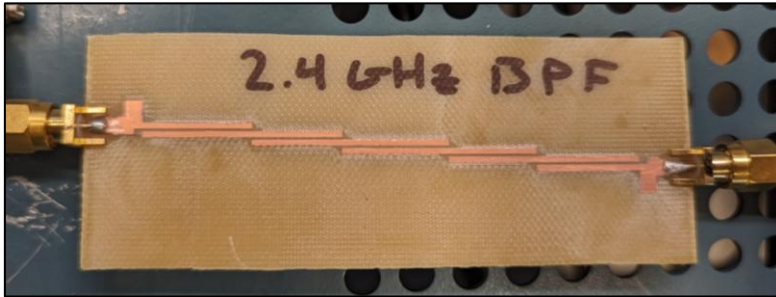
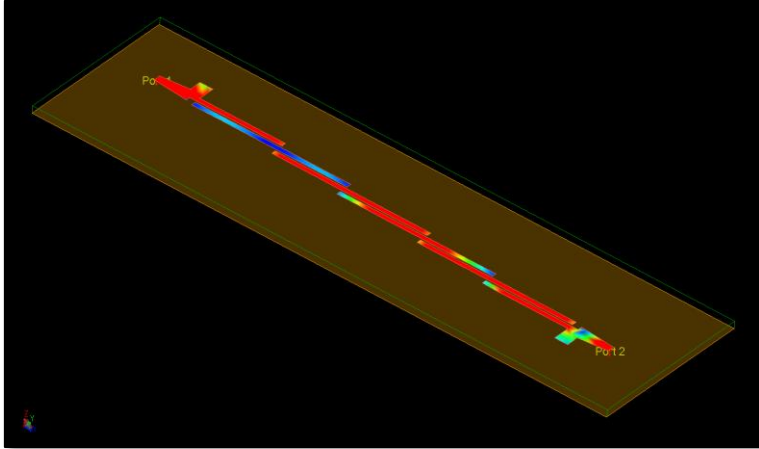
# Microstrip Devices

## L-Band Stub Low Pass Filter



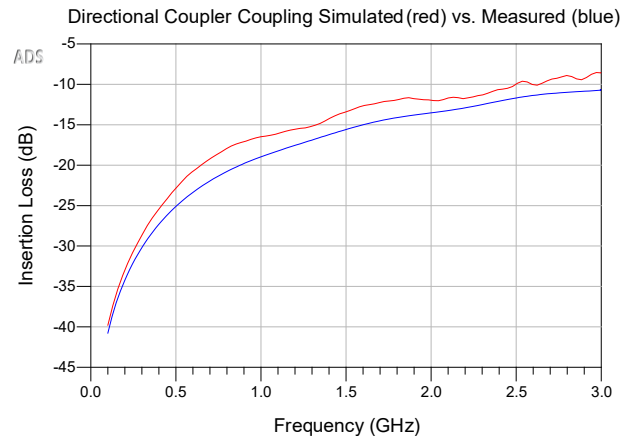
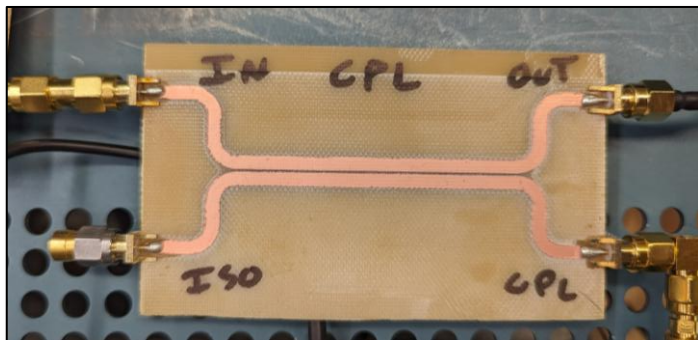
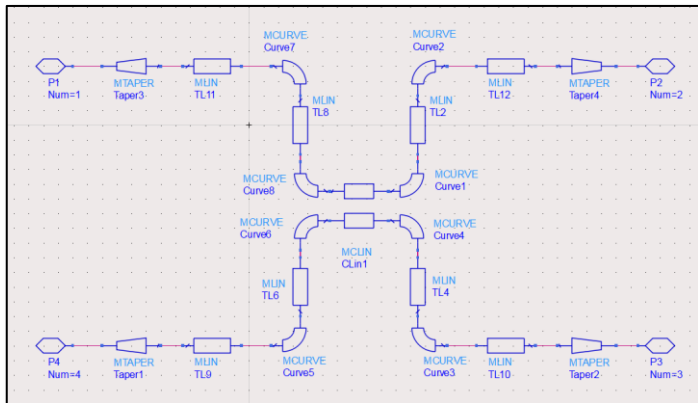
# Microstrip Devices

## S-Band Coupled Line Band Pass Filter

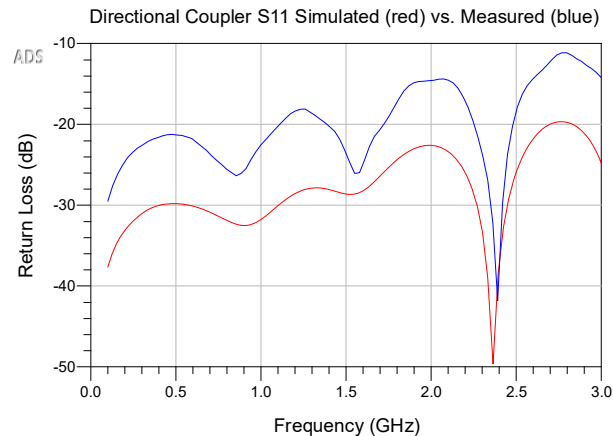


# Microstrip Devices

## S-Band Directional Coupler



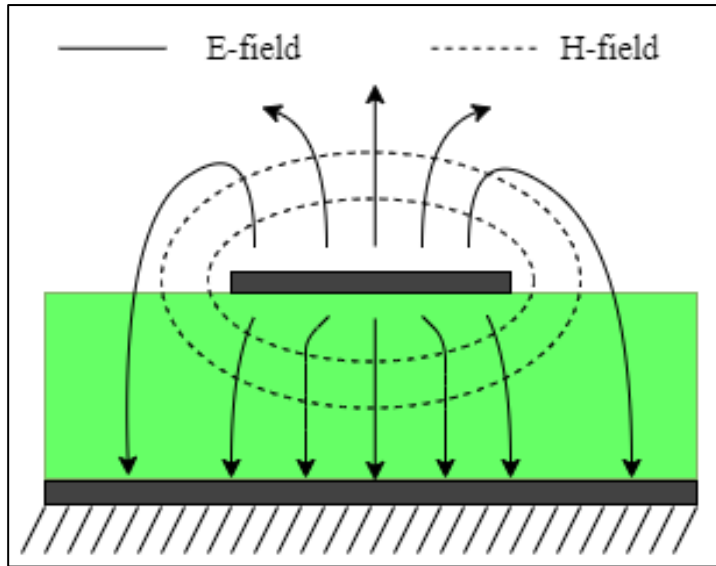
Same principle as the coupling microstrips!



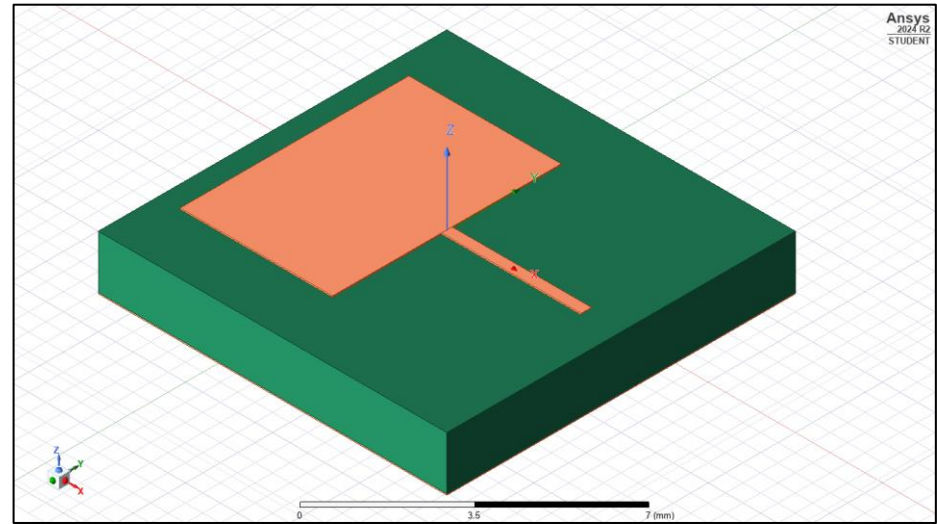
# Microstrip Devices

## Patch Antennas

Recall how the microstrip has  
fringing fields?



We can use the fringing fields to radiate  
power → Microstrip Antenna!

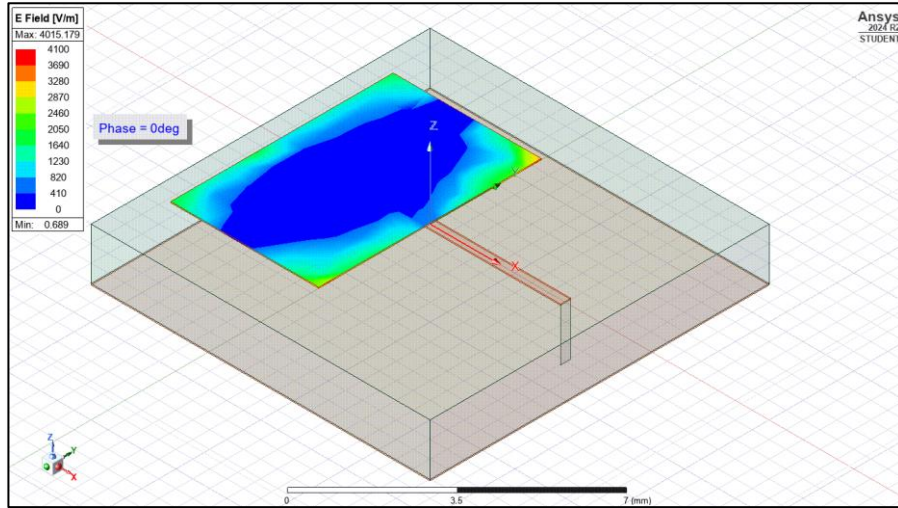


<https://www.signalintegrityjournal.com/articles/2378-measuring-the-bulk-dielectric-constant-dk-on-a-microstrip-with-a-tdr>

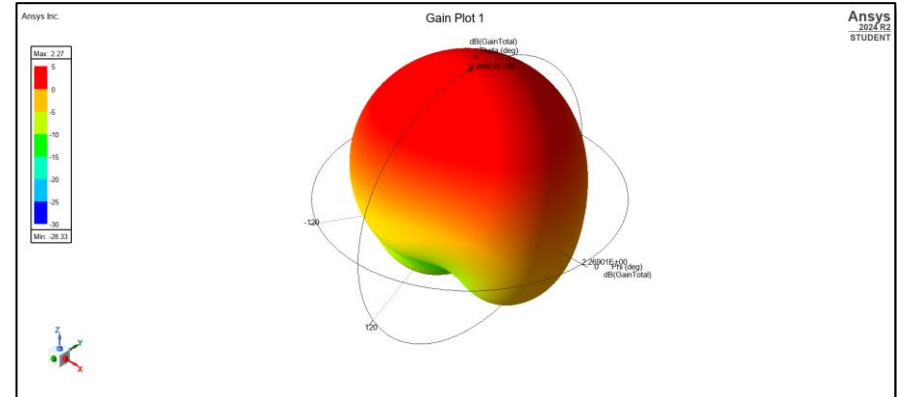
# Microstrip Devices

## Patch Antennas

Creating a resonating wave in the microstrip patch results in changing fringing fields



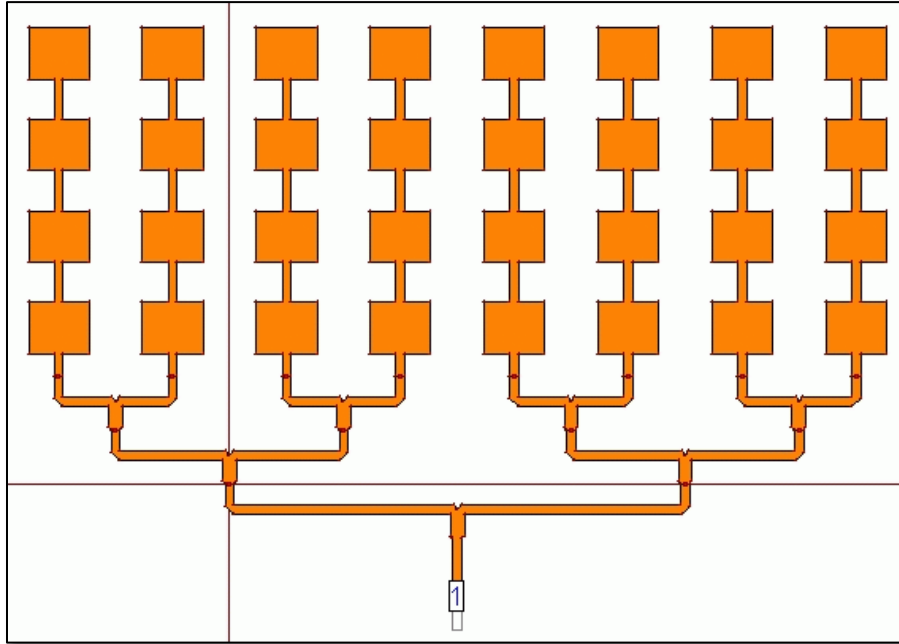
Fringing fields form a far-field radiation pattern



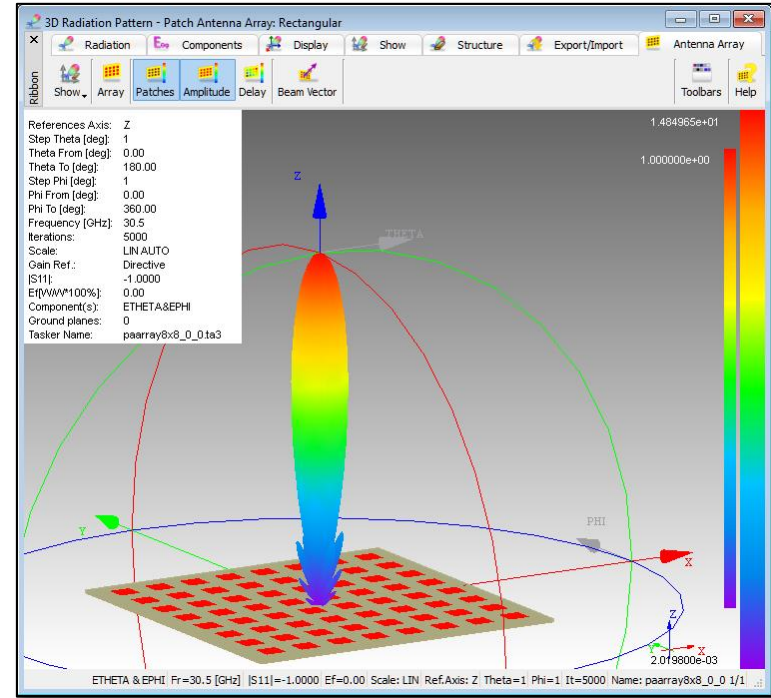


# Microstrip Devices

## Patch Antenna Arrays



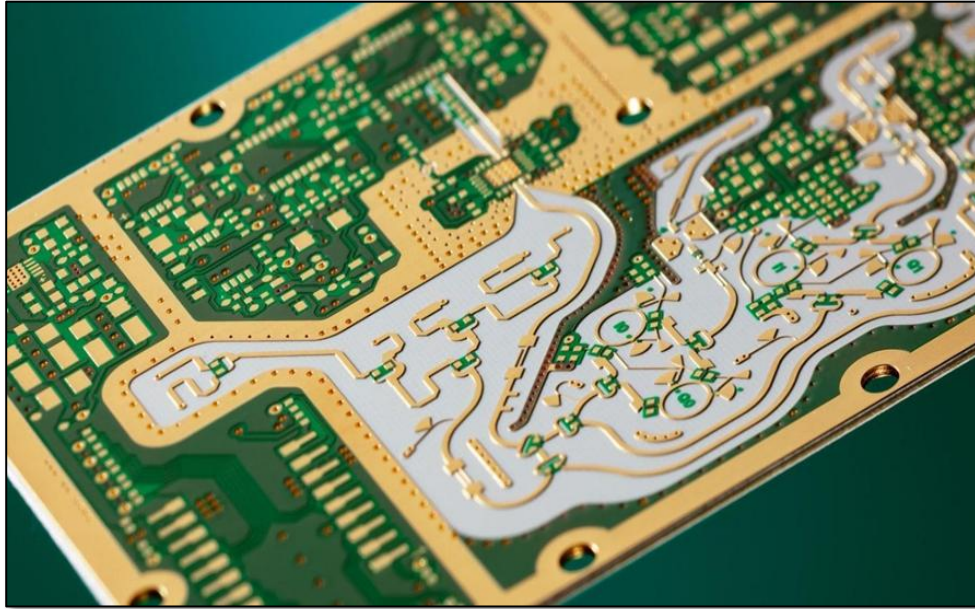
[https://www.researchgate.net/figure/Series-fed-patch-antenna-array-for-60-GHz-Both-developed-antenna-arrays-have-minimum\\_fig4\\_267718251](https://www.researchgate.net/figure/Series-fed-patch-antenna-array-for-60-GHz-Both-developed-antenna-arrays-have-minimum_fig4_267718251)



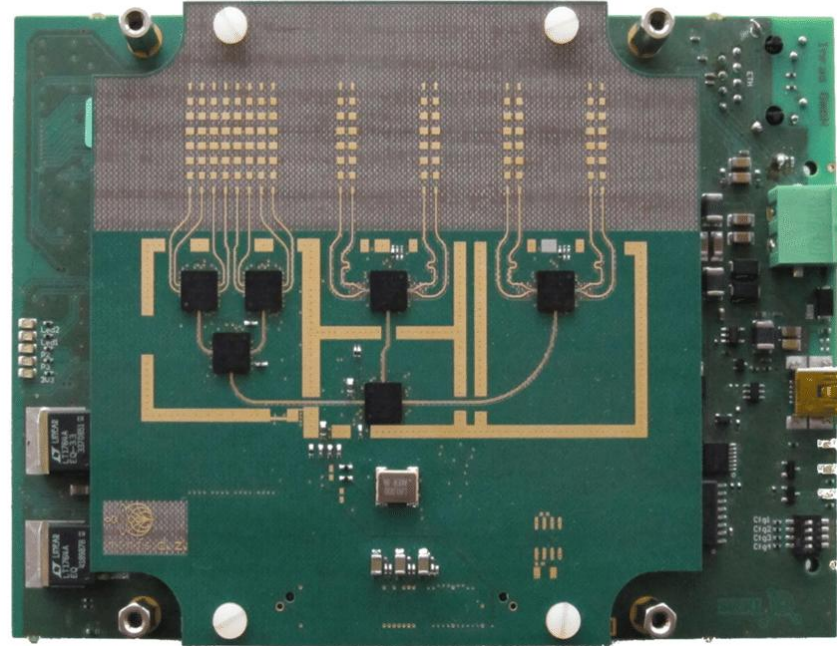
[https://www.qwed.eu/QuickWave/help/qw-modeller\\_examples\\_guide/15\\_rectangular\\_patch\\_antenna\\_8x8\\_array.htm](https://www.qwed.eu/QuickWave/help/qw-modeller_examples_guide/15_rectangular_patch_antenna_8x8_array.htm)



# Integrated Microwave Assemblies



<https://www.viasion.com/radar-pcb/>



[https://www.researchgate.net/figure/mage-of-the-radar-system-The-PCB-on-top-is-the-RF-frontend-which-holds-the-RF\\_fig2\\_313686839](https://www.researchgate.net/figure/mage-of-the-radar-system-The-PCB-on-top-is-the-RF-frontend-which-holds-the-RF_fig2_313686839)